

Welcome to Mycronic's Capital Markets Day!

Today's speakers



Sven Chetkovich
Director Investor Relations,
employed since 2017



Anders Lindqvist
President and CEO,
employed since 2019



Pierre Brorsson
CFO and Sr VP Corporate
Development, employed since 2021



Lena Båvegård
Sr VP Global Functions,
employed since 2018



Charlott Samuelsson
Sr VP Pattern Generators,
employed since 1996



Mikael Wahlsten
Head of PG Product Strategy and
Development, employed since 2003



Clemens Jargon
Sr VP PCB Assembly Solutions,
employed since 2015



Ivan Li
Sr VP High Volume,
employed since 2008



Magnus Marthinsson
Sr VP Global Technologies,
employed since 2004

Agenda

- 13:00 Opening and introduction:** Sven Chetkovich, Director Investor Relations
- 13:02 Strategy, new financial targets, sustainability:** Anders Lindqvist, President and CEO, Pierre Brorsson, CFO and Sr VP Corporate Development, Lena Båvegård, Sr VP Global Functions
- 13:25 Pattern Generators:** Charlott Samuelsson, Sr VP Pattern Generators, Mikael Wahlsten, Head of Product Strategy & Development, Pattern Generators
- 13:55 PCB Assembly Solutions:** Clemens Jargon, Sr VP PCB Assembly Solutions
- 14:15 Break**
- 14:20 High Volume:** Ivan Li, Sr VP High Volume
- 14:40 Global Technologies:** Magnus Marthinsson, Sr VP Global Technologies
- 15:10 Mycronic today and tomorrow:** Anders Lindqvist, President and CEO
- 15:15 Q&A**
- 15:30** Production tour, three parallel groups
- New inspection tool, IQX, 20 minutes
 - New SLX, 20 minutes
 - Prexision 8000 Evo, 20 minutes
- 16:30** End of Capital Markets Day



Live stream

**Capital
Markets
Day 2026**

Capital Markets Day 2026

Anders Lindqvist

President and CEO

Capital Markets Day 2026

Lena Båvegård

Sr VP Global functions

VISION

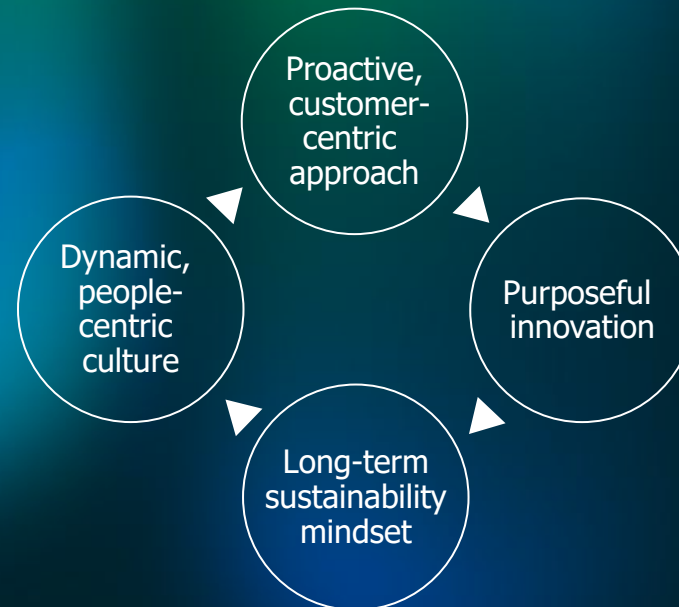
**To be the most trusted partner to
the creators of tomorrow's electronics**

WHO WE ARE

Market leading solutions provider

- for electronics production
- in selected niches
- with high degree of recurring revenue

OUR PRINCIPLES



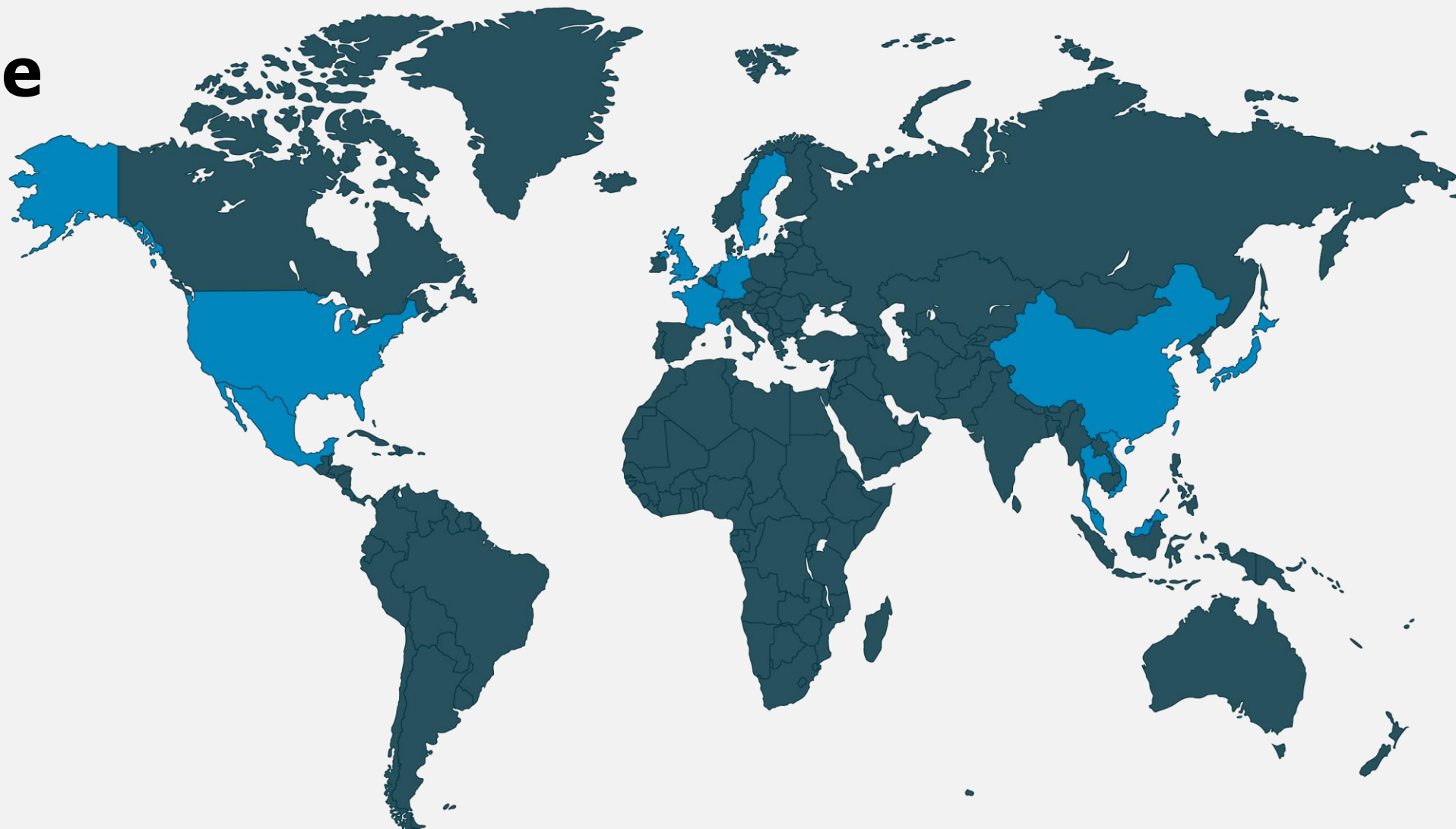
OUR AMBITION

Sustainable profitable growth

- Continued high focus on growth
- Ensuring growth is profitable, responsible and resilient

Worldwide footprint

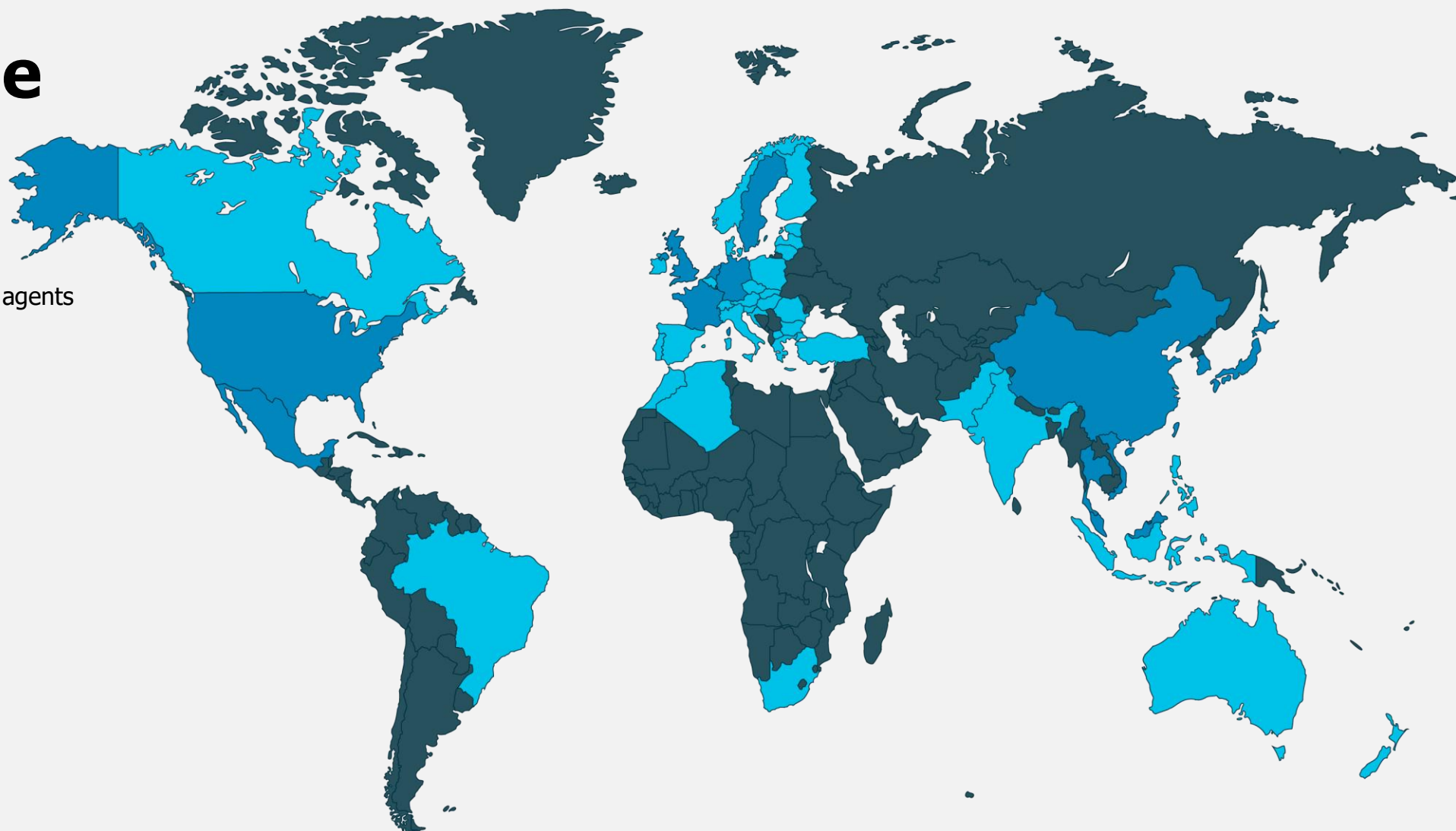
■ Myconic subsidiaries



Worldwide footprint

- Mycronic subsidiaries
- Mycronic distributors and agents

+50
Mycronic is represented in
more than 50 countries



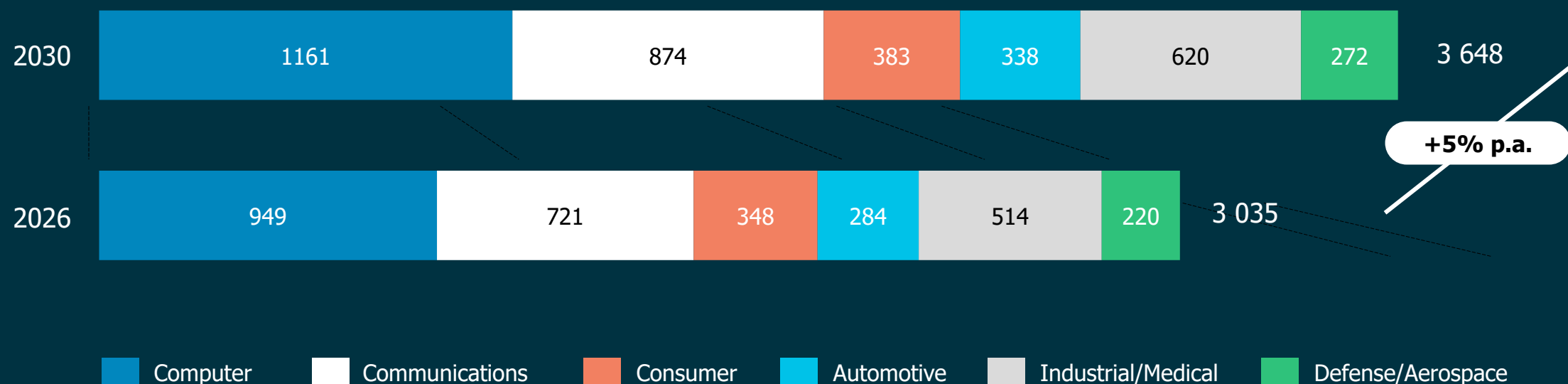
Capital Markets Day 2026

Anders Lindqvist

President and CEO

Mycronic is serving and enabling a fast-growing industry

Electronics systems market growth is fueled by strong trends



Source: Prismark Mar 2026 (USD billion)

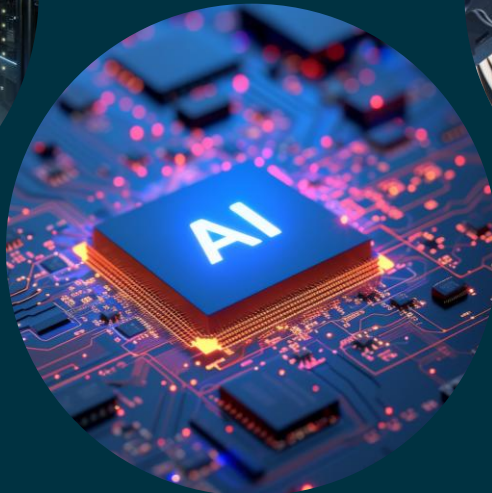
Note: Server/data storage part of "Computer" segment

Mycronic is serving and enabling a fast-growing industry

Electronics systems market growth is fueled by strong trends



**AI servers and
data centers**



AI



Electrification



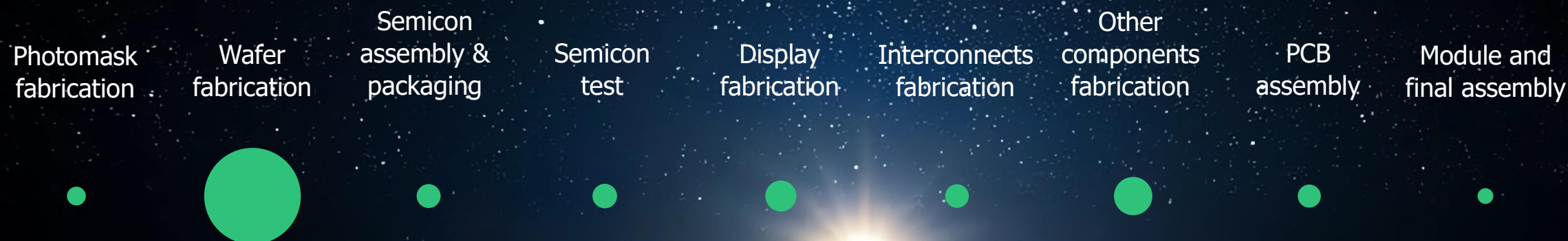
Automation



Geopolitics

Succeeding in an industry with USD 200 billion capex

Decentralized operating model to enable close and fast collaboration with customers



Addressing attractive niches

- Growth
- Profitability
- Differentiation

Targeting market segment leadership

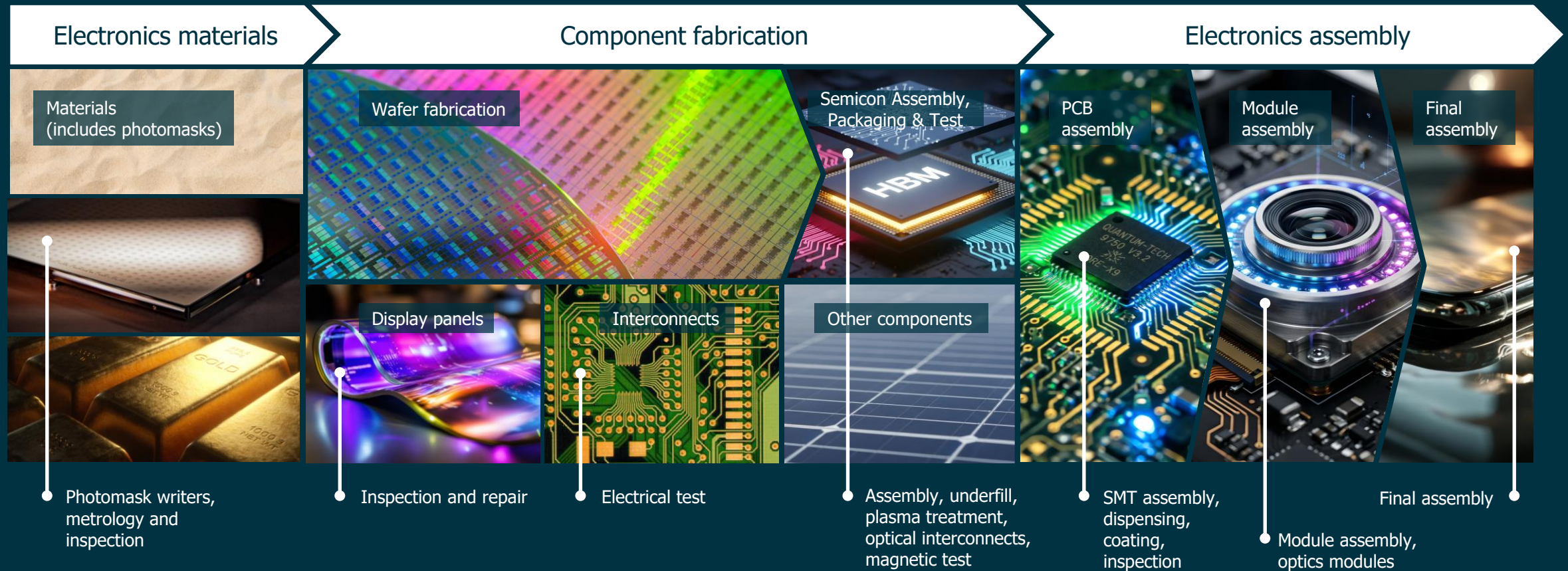
Made possible through close collaboration with leading customers in a decentralized operating structure

Circle areas represent capex in the electronics manufacturing value chain

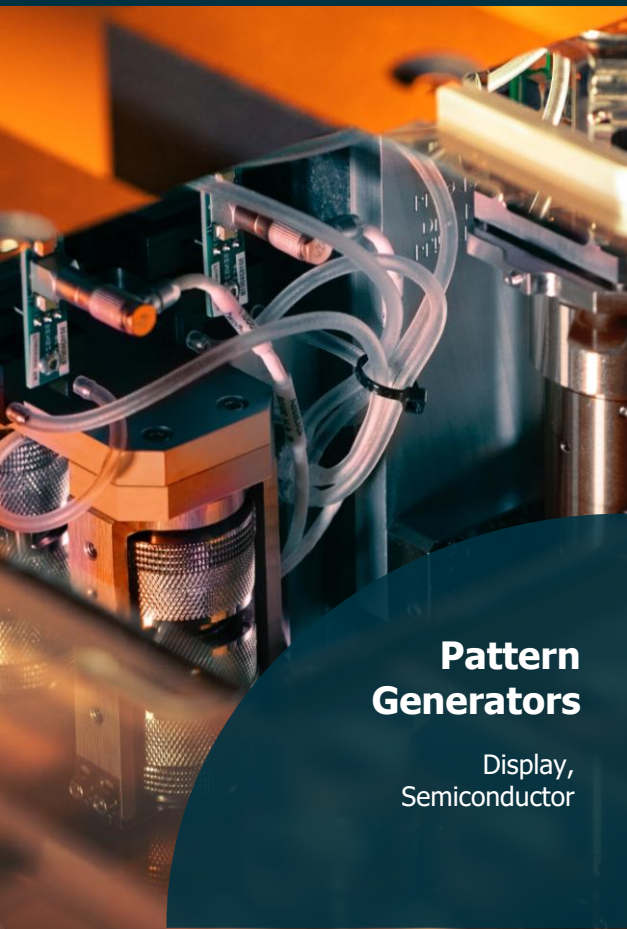
Source: Prismark May 2024, and Mycronic estimates

Targeting leadership in attractive niches in the value chain

Supplying equipment to bring tomorrow's electronics to life



Mycronic's **four divisions** – with clear divisional focus



Pattern Generators

Display,
Semiconductor



PCB Assembly Solutions

Medical, Industrial,
Automotive,
Aerospace & Defense



High Volume

Semiconductor,
Automotive,
Consumer



Global Technologies

Telecom/Datacom,
Aerospace & Defense,
Automotive, Medical,
Semiconductor, Consumer

Mycronic's **four divisions** – with clear divisional focus

Number one
Patterning Solutions
company in selected
segments

Pattern Generators

Display,
Semiconductor

Number one
high flex solutions
provider for PCB
Assembly

PCB Assembly Solutions

Medical, Industrial,
Automotive,
Aerospace & Defense

Number one high
volume assembly
solutions provider
for electronics
production with core
in dispensing

High Volume

Semiconductor,
Automotive,
Consumer

**Technology
and market** leader
in attractive
electronics niches

Global Technologies

Telecom/Datacom,
Aerospace & Defense,
Automotive, Medical,
Semiconductor, Consumer

Capital Markets Day 2026

Pierre Brorsson

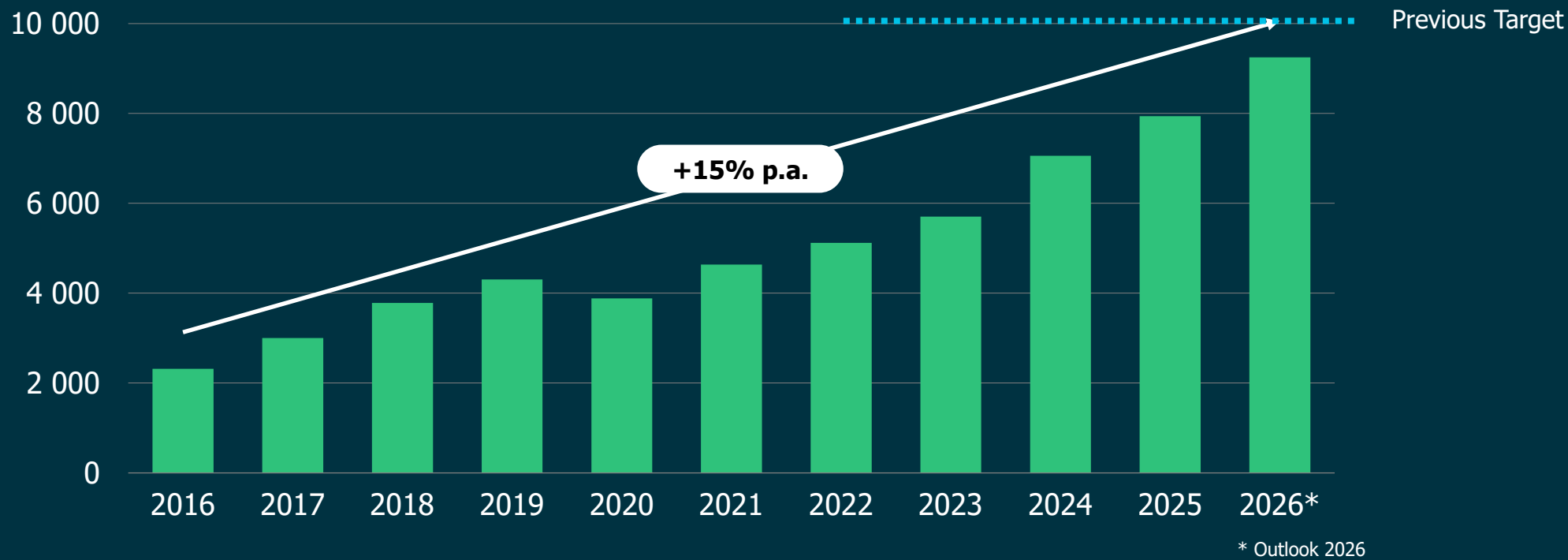
CFO and Sr VP Corporate Development

Financial and sustainability development

Strong and improved performance over time – Previous Financial targets within reach

Net sales

MSEK

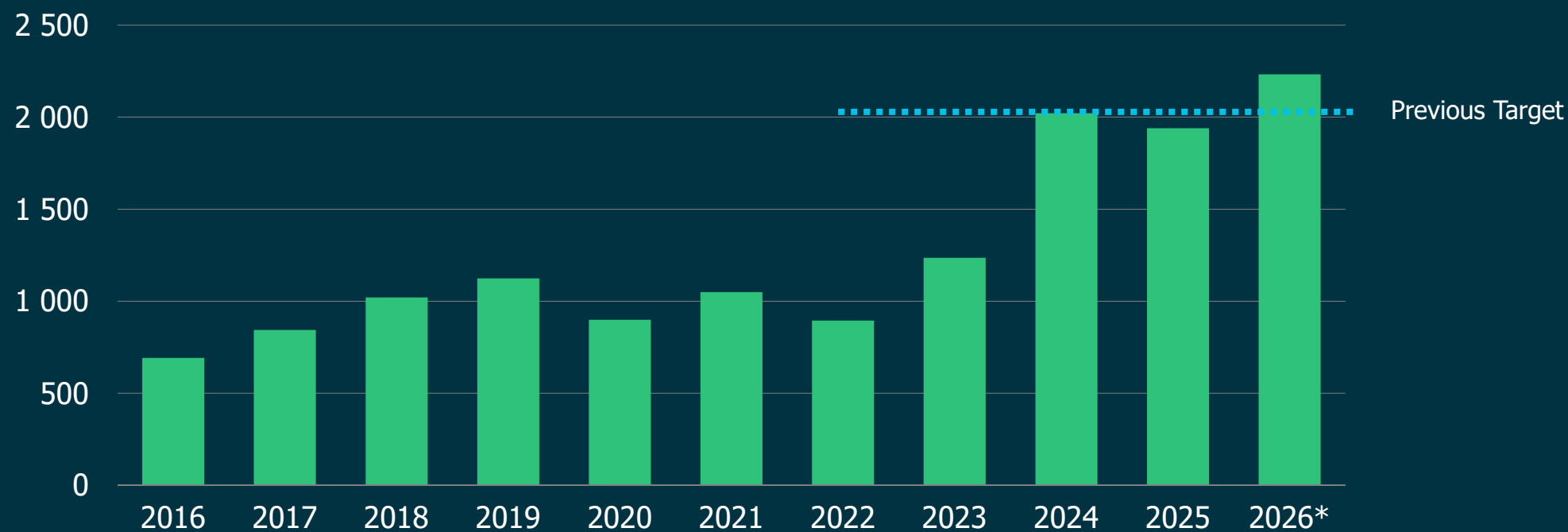


Financial and sustainability development

Strong and improved performance over time – Previous Financial targets within reach

EBIT

MSEK



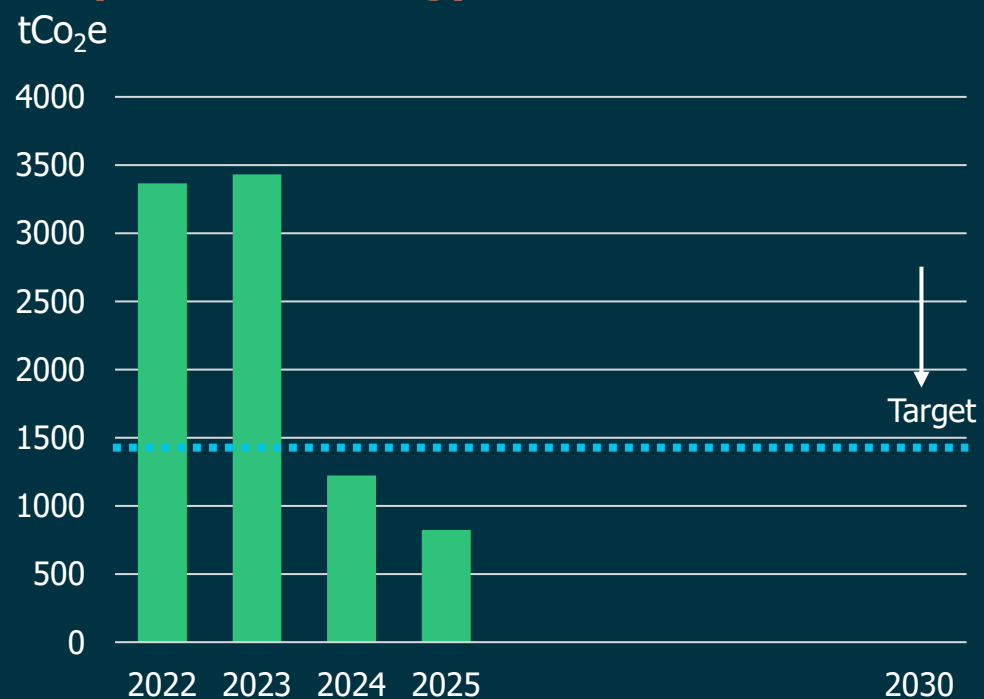
* R12 June 2026

Financial and sustainability development

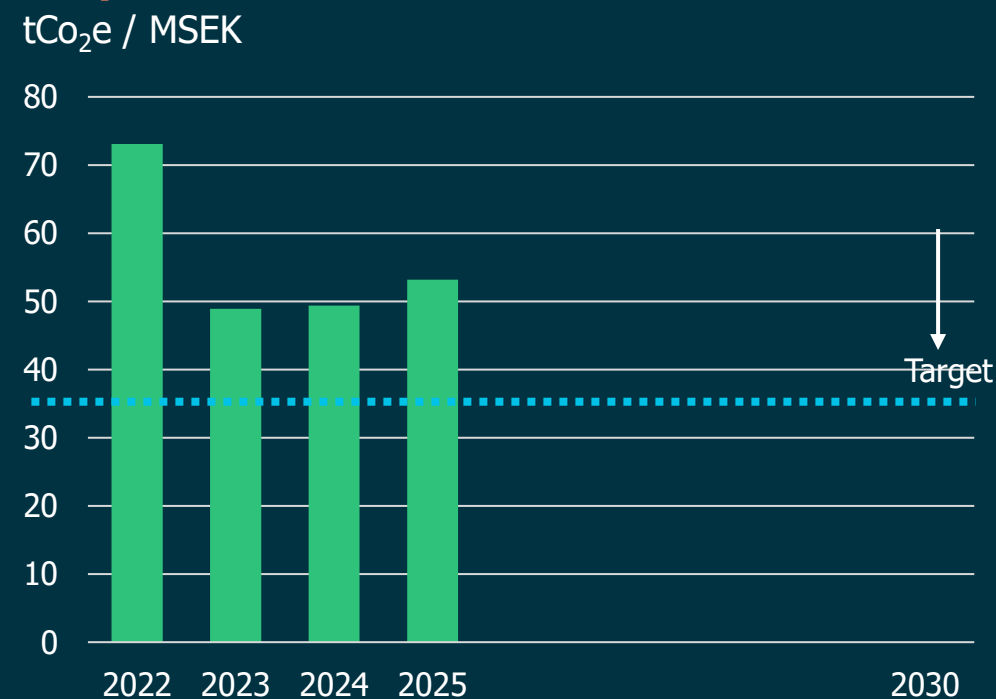
Improved performance over time – Scope 1 & 2 target achieved

Climate

Scope 1 & 2 – Energy emissions



Scope 3 – Product use emissions



Recap Capital Markets Day 2022

On-track to fulfill our ambitions

Closing in

Net sales SEK 10 billion 2027-2030

Reached

**EBIT SEK 2 billion 2027-2030
and always above 20% from
2023**

On a good track

Sustainability targets

- Energy use emissions reached
- Product use emissions improving

Partly reached

All divisions above 10%

- Reached in 2023 and 2024 but PCB Assembly solutions now behind – actions taken

Largely reached

Active M&A agenda

- Several relevant technology and bolt-on acquisitions made
- No transformational transactions closed to date

Reached

**High growth in
sales and profits also outside
Pattern Generators**

Long-term financial and sustainability targets

TO BE ACHIEVED BY 2032-2035 (NEW)

Net sales to reach SEK 20 billion

EBIT margin to remain around 25 percent

TO BE ACHIEVED BY 2030 (REMAIN)

Climate footprint will be cut by half¹

The greenhouse gas emissions related to our operations and adjusted for future acquisitions shall be reduced as follows (with 2022 as the base year):

- Absolute Scope 1 and 2 greenhouse gas emissions shall be reduced by 56%
- Relative Scope 3 greenhouse gas emissions from the use of sold products shall be reduced by 52% per SEK gross profit



Mycronic execution going forward

Strong development rooted in the divisional structure

Pattern Generators

- Broaden and diversify leadership position within laser mask writing
- Expand offering in inspection and repair and enter wafer (inspection and clean)
- Solid growth from new business at lower than historic EBIT margins

PCB Assembly Solutions

- Focus on a profitable core, profitability improvement program initiated
- Limited growth and targeting EBIT margins above 10%

High Volume

- Expand product offering as well as geographical footprint
- High growth and targeting EBIT margins (excl ESOP costs) of ~20%

Global Technologies

- Capitalize on investments in AI infrastructure and maintain leading positions
- Further develop acquired technologies
- Continue to add new technologies
- Solid growth and targeting EBIT margins of ~30%

Active M&A agenda

- Continue with technology and bolt-on acquisitions as well as exploring larger opportunities
- Prioritize semiconductor-related technologies

Sustainability

- Innovate to increase product efficiency
- Invest in modern, energy-efficient facilities
- Collaborate with industry peers to reduce climate impact
- Ensure responsible business

Mycronic's M&A deal strategy

Target segmentation



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DIVISION

Pattern Generators

Charlott Samuelsson

Sr VP Pattern Generators

Mikael Wahlsten

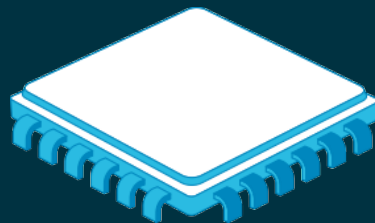
Head of Product Strategy and Development, Pattern Generators

The link between design and mass production

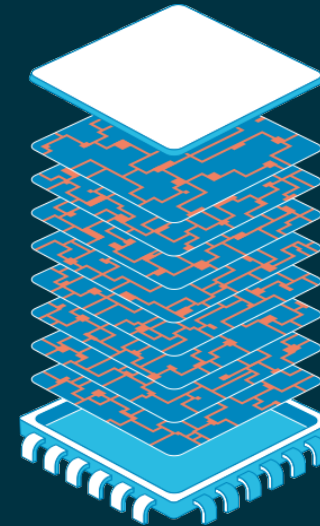
Photomasks - enable high-volume production yield

Lithography using photomasks is a technology very suitable for high-volume manufacturing:

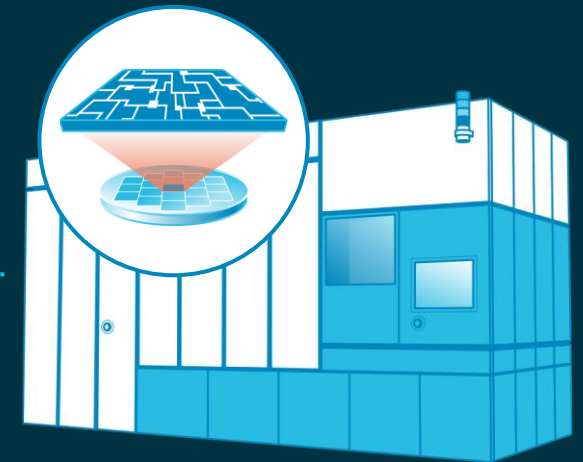
- When all is in place there is low risk for problems or disturbances during production.
- Cost scales very well with volume.
- Proven technology developed and fine-tuned over decades.



- Advanced electrical circuits and displays consist of multiple layers – each layer demanding a photomask.



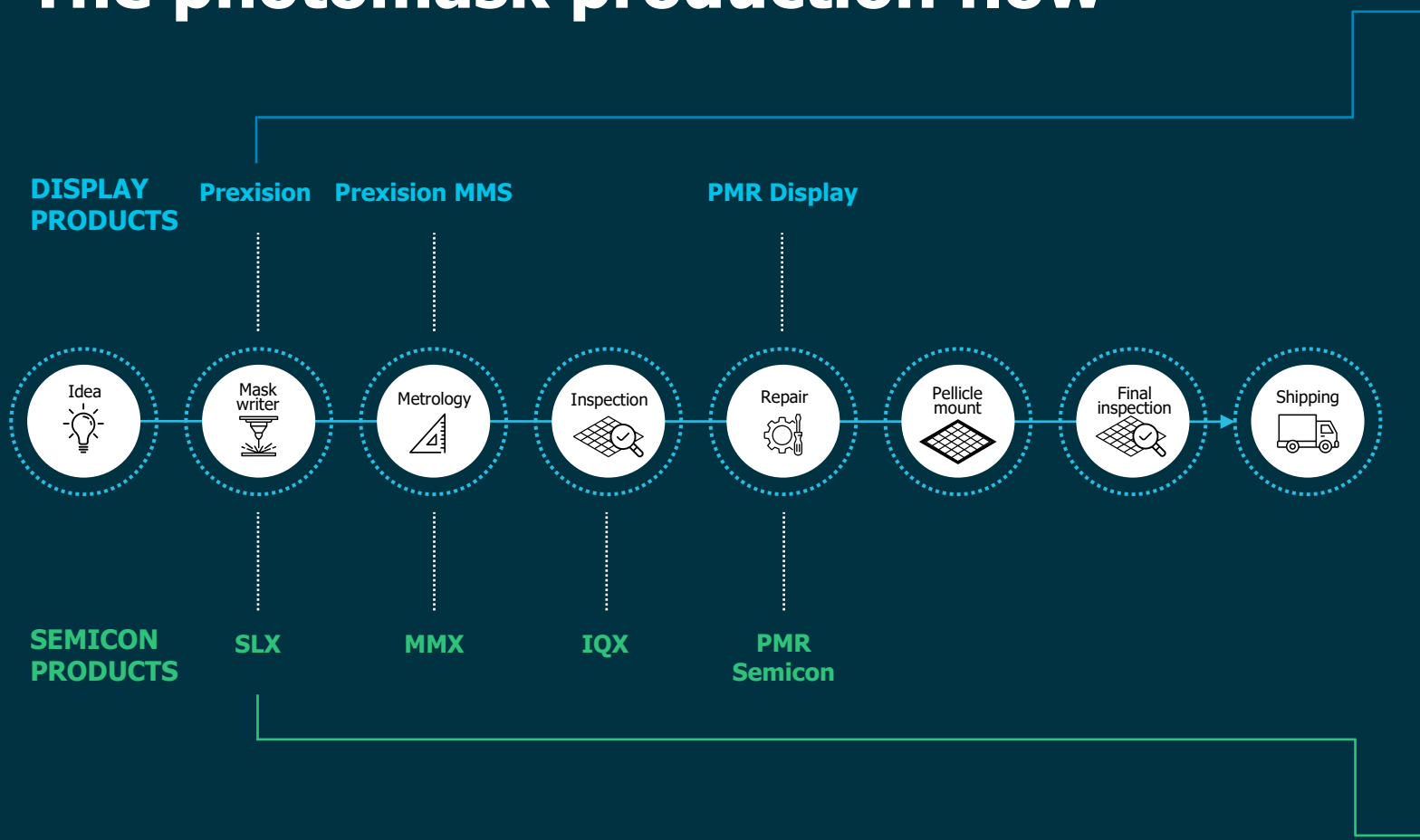
- Advanced semiconductor devices can contain up to around 100 individual layers, with some structures smaller than 10-20 nm.
- Displays typically contain 10–20 layers, with the smallest structures around 700 nm.



- Each layer is defined by copying a separate photomask in the stepper/aligner.

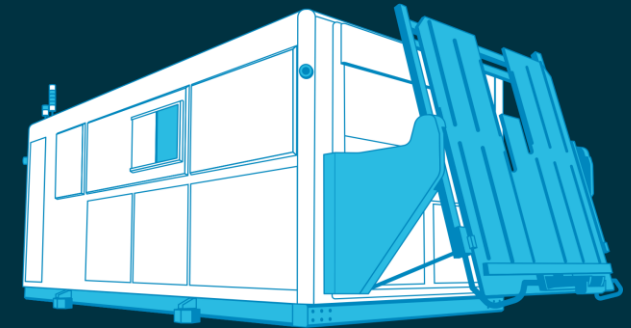
At the heart of electronics manufacturing

The photomask production flow



70 mask writers support a USD 130 billion display industry.

Mask writer – writes the photomask



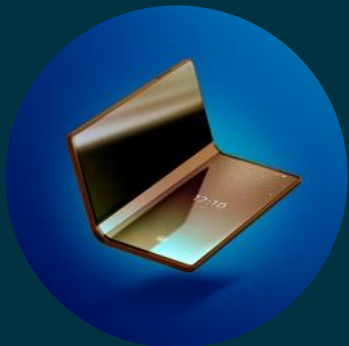
- The photomask that takes hours, for display masks even days, to produce by the mask writer is copied within seconds in production of semicon and displays.
- Few but typically large companies constitute the customer base. Two type of customers, Captive (in-house production) and Merchant.

500 mask writers support a USD 770 billion semiconductor industry.

Serving two photomask markets - display & semiconductors

Long-term persistent trends drive both markets in a positive direction

Display Trends



Display size, form factor, functionality and power consumption



Higher quality displays and transition to OLED also for larger displays



Displays in new applications and differentiation

Semicon Trends



Electrification of everything



AI, big data, cloud and edge computing solutions



Data communication (5G, fiber etc.)

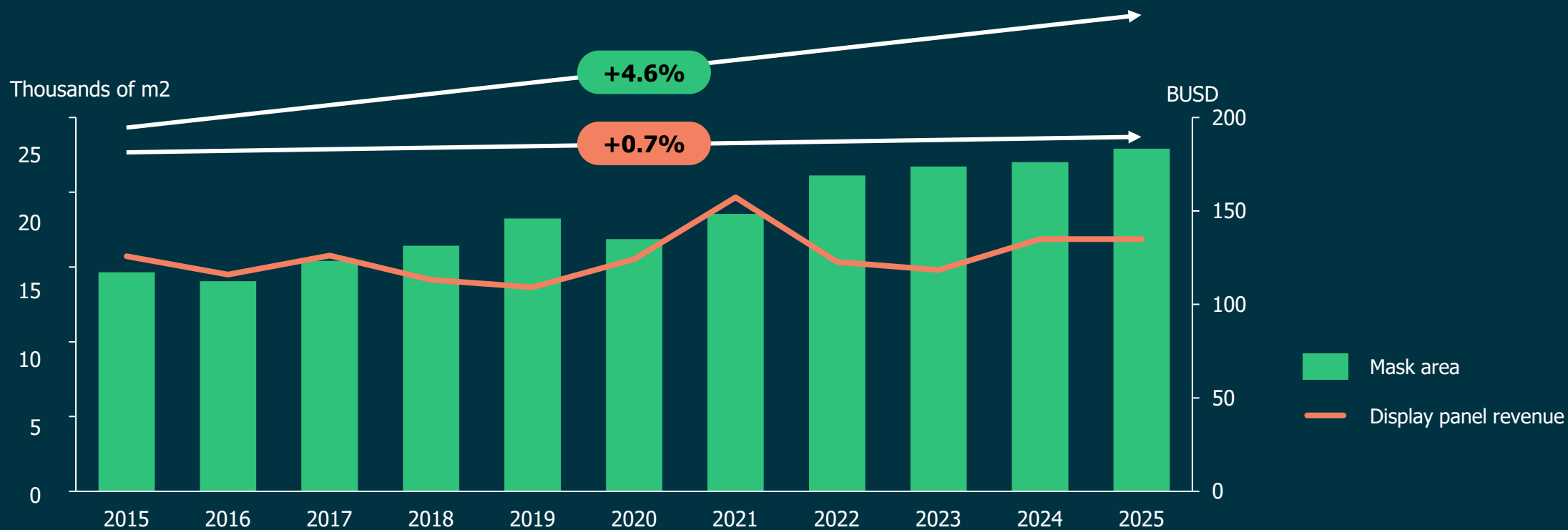
General drivers for photomask market

New product designs and applications
Research and product development activities
Number of new steppers/aligners
More advanced products requiring more photomasks per designs

Photomask market dynamics – illustrated for display

Historical development shows more steady growth vs end-market, increased photomask area needed

Display photomask area development vs display panel revenue¹

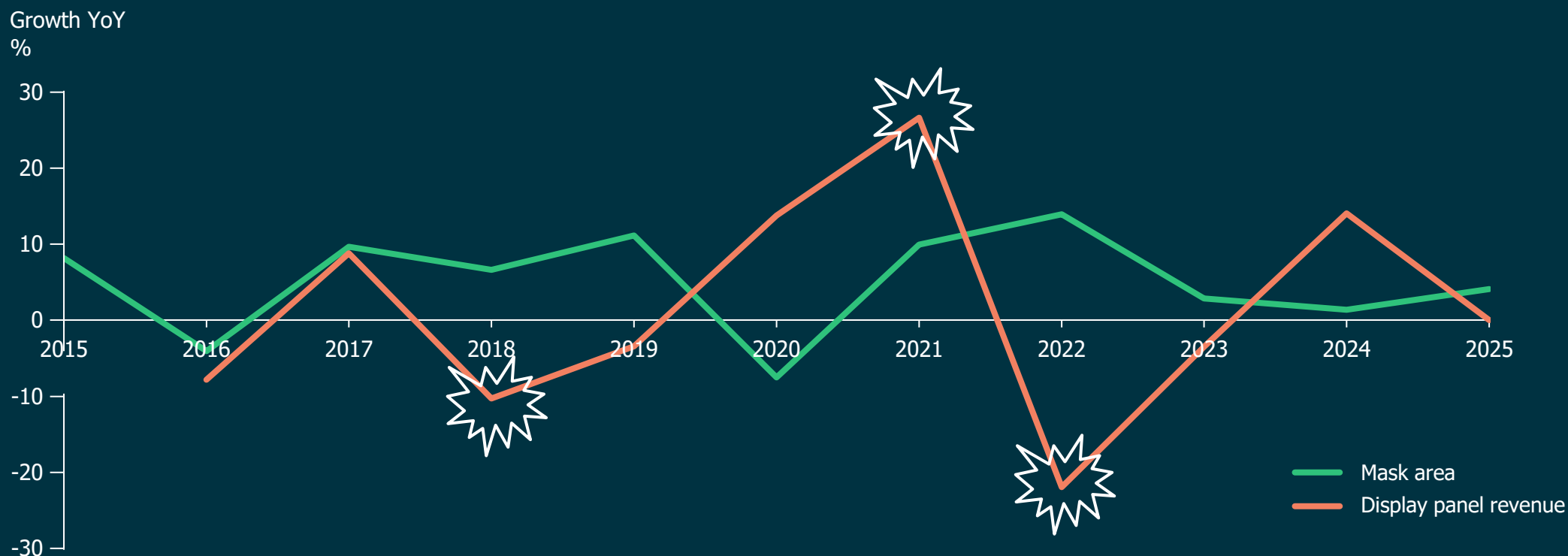


1) Omdia, April and July, 2026

Photomask market dynamics – illustrated for display

Historical development shows greater stability vs end-market, no strong direct correlation observed

Display photomask area and display panel revenue YoY growth development¹



1) Omdia, April and July, 2026

Photomask market dynamics – illustrated for display

Steady growth & greater stability vs end-market, equipment needs also driven by strategic decisions

Market for photomasks

– Usually a more stable growing market than the end-markets

- Long-term, market growth primarily driven by product diversification and more advanced designs, requiring additional photomasks
- Photomask demand is generally showing less variations than end-markets. R&D investments and new product development, during industry downturns, mildening the largest swings

Market for equipment

– Driven both by photomask market demand and customers' strategic decisions

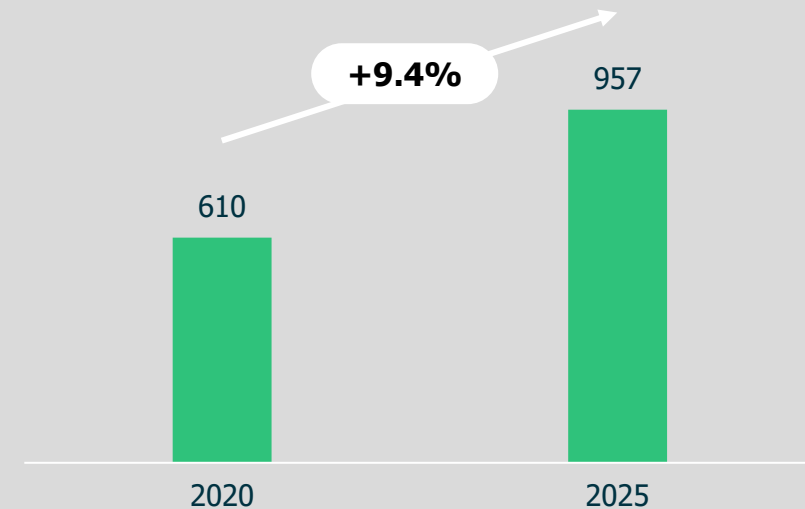
- Individual customers' long-term strategic decisions regarding geographical footprint, supply chain resilience and IP protection, often equally important drivers for investment size and timing as the overall market development for photomasks

Aftermarket business

A robust, growing, profitable base – creates stability and enables long-term business perspective

- Premium customer-centric support through a global, highly skilled service organization close to customers, serving both semiconductor and display mask writers
- Recurring all-inclusive MYCare service contracts
- Attractive trade-in opportunities for installed base
- Value adding aftermarket offering for sustainability during product use
- Well-established global operation for growing business with additional new products and markets
- Growing installed base of semicon tools will continue to fuel stable growth in the coming years

Aftermarket development for Pattern Generators over time (SEK million)



Installed base of systems*

200

Aftermarket of total sales*:

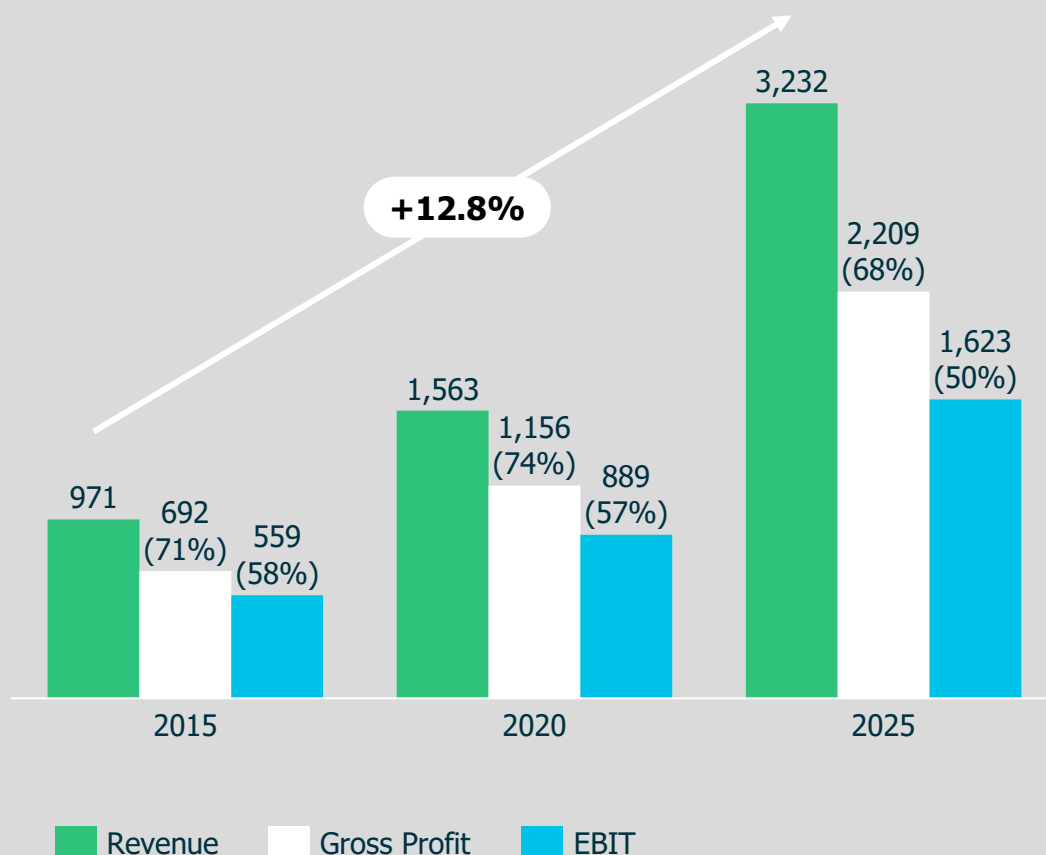
~30%

100%

All systems supported by service contract or under warranty *

*) Excluding Cowin

Business development for Pattern Generators over time (SEK million)



The journey – Expansion to new markets

2015-2020

- Mainly serving display photomask market
- Optimizing business and grow with the market
- Large year-to-year variation

2020-2025

- Re-entered semicon with first SLX and later MMX
- Expanding in a positive market and gaining market share
- Less year-to-year variation due to more diversified business
- Good growth in absolute terms. The margin decline reflects the expansion into markets with increased competition with large established players

2026 and beyond

- Further expanding into adjacent applications by capitalizing on synergies, technologies, and resources
- Targeted M&A to enable and accelerate growth
- Expected additional growth and profits, although margins will likely continue to decline

2026 and beyond - The next phase of growth

Continue enabling display, expand in semicon and address new opportunities outside photomasks

Display Photomask

Enable leading edge and maintain position in mainstream segments



- Full portfolio of photomask writers, in additions solutions for metrology and repair
- Incrementally develop new and increased capabilities while maintaining platform stability
- Actively maintain and support a modern installed base

Semicon Photomask

Broaden portfolio with focus on mainstream semicon



- Expand mask writer portfolio with metrology, repair, and the new inspection, for the mainstream market
- Unlock additional customer value in automation and connected tools
- Long-term commitment to push performance through continuous platform development

Expand beyond photomask

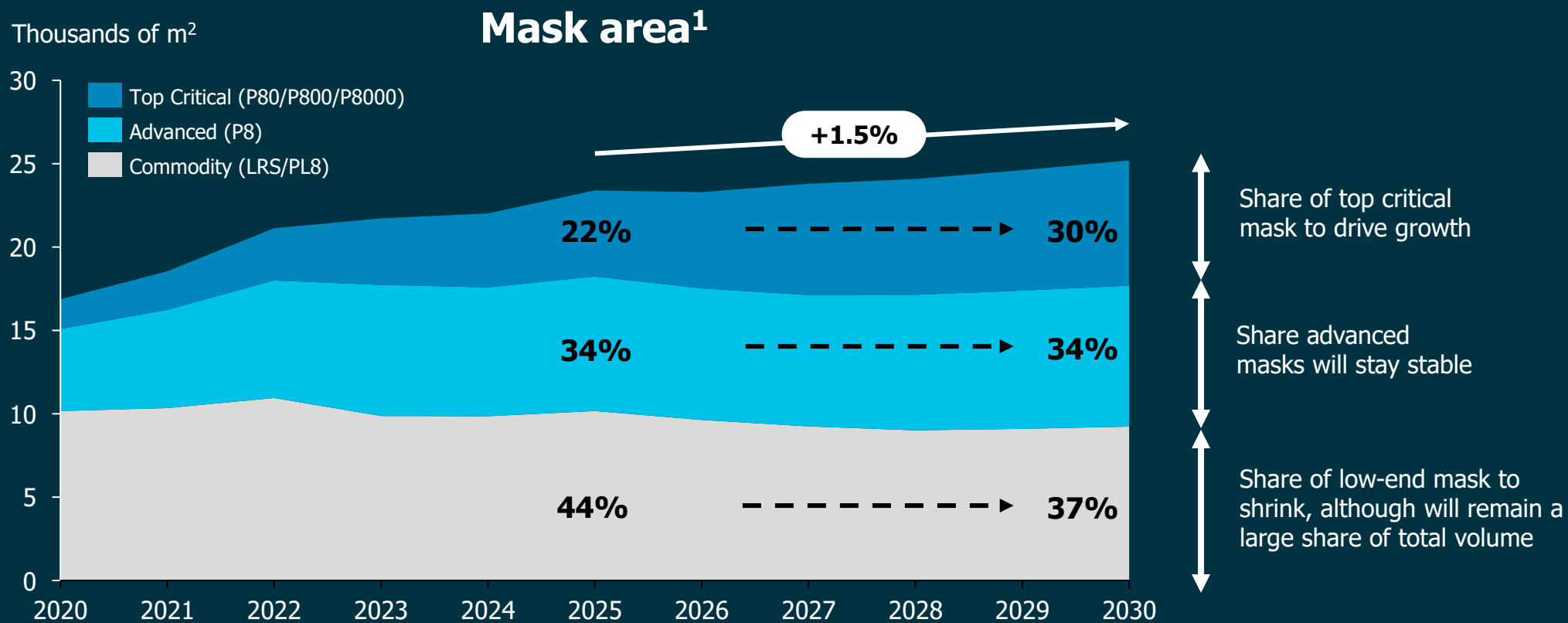
Leverage our technology for new applications and markets



- Leverage existing core technologies and resources to find new applications and opportunities
- Primary focus on wafer backend and packaging applications where there is a potential to establish a leading position long-term

Display photomask market trends in the coming years

Continued growth, with advanced segments outperforming, driving demand for high-end writers

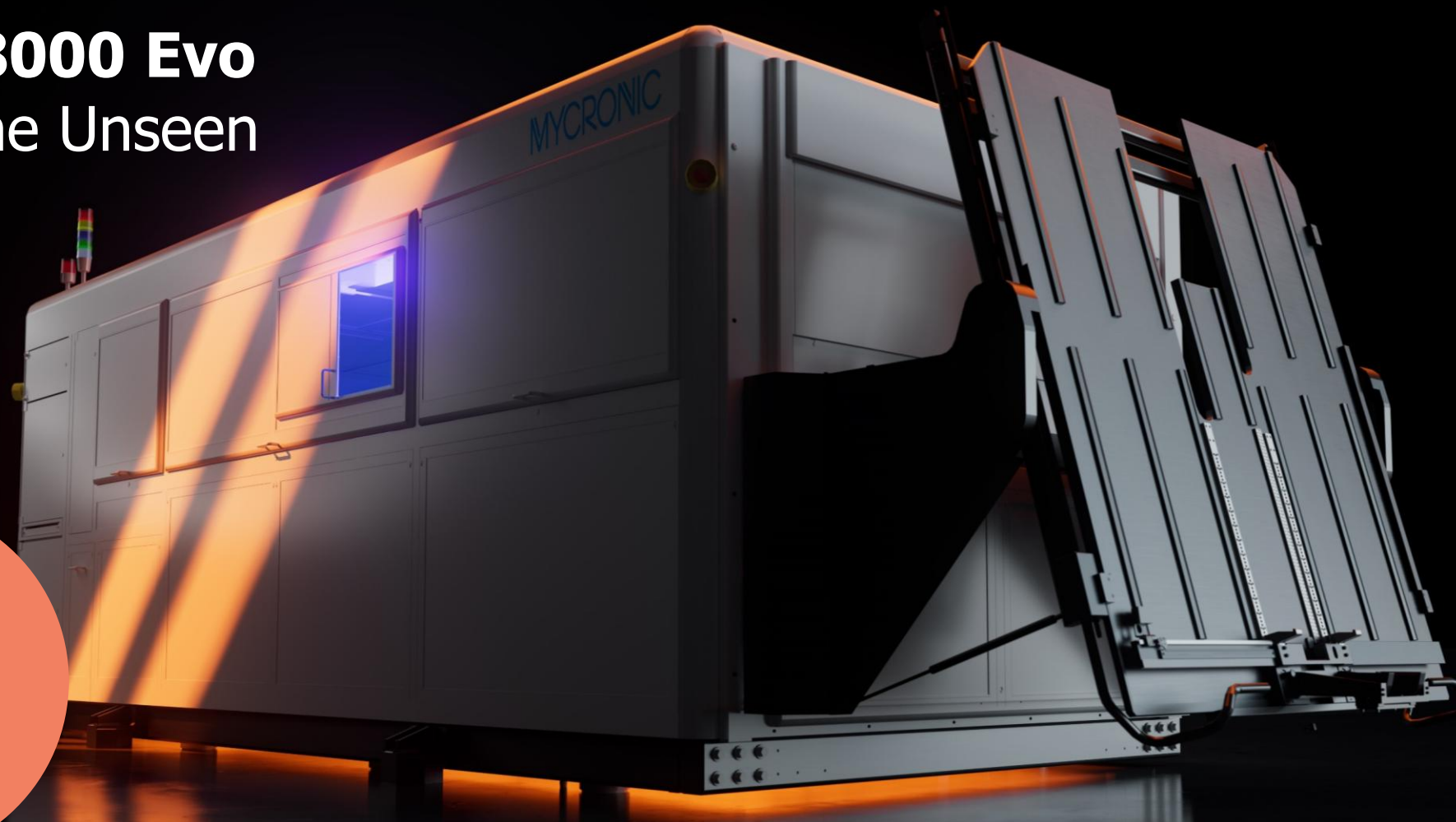


1) Omdia, July, 2026 & Mycronic estimates

Prexision 8000 Evo

– Unleash the Unseen

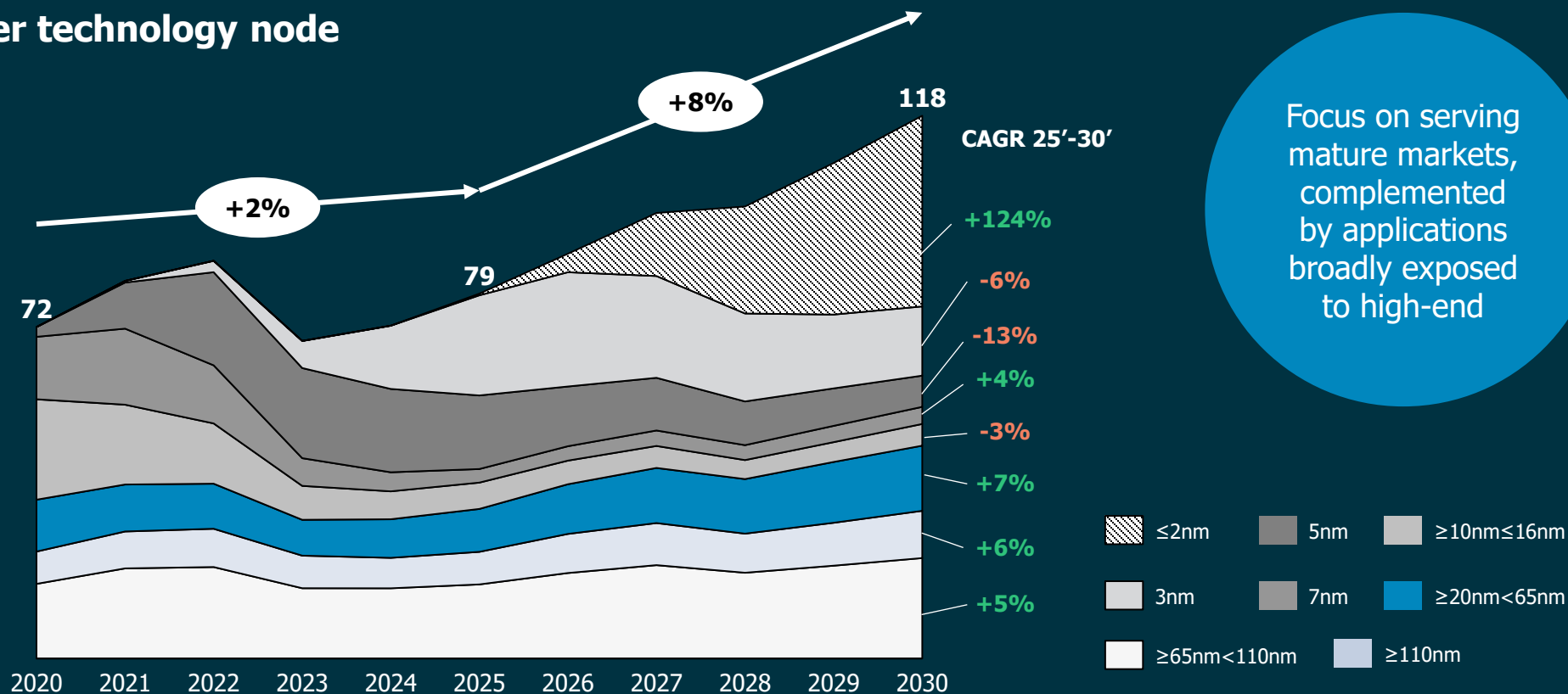
Launched in
April 2024
First system
delivered in Q1
2026



Semicon photomask market trends and our strategy

Steady wafer growth at mature nodes, and strong high-end growth “jumping” node to node

Wafer starts per technology node Million Units¹

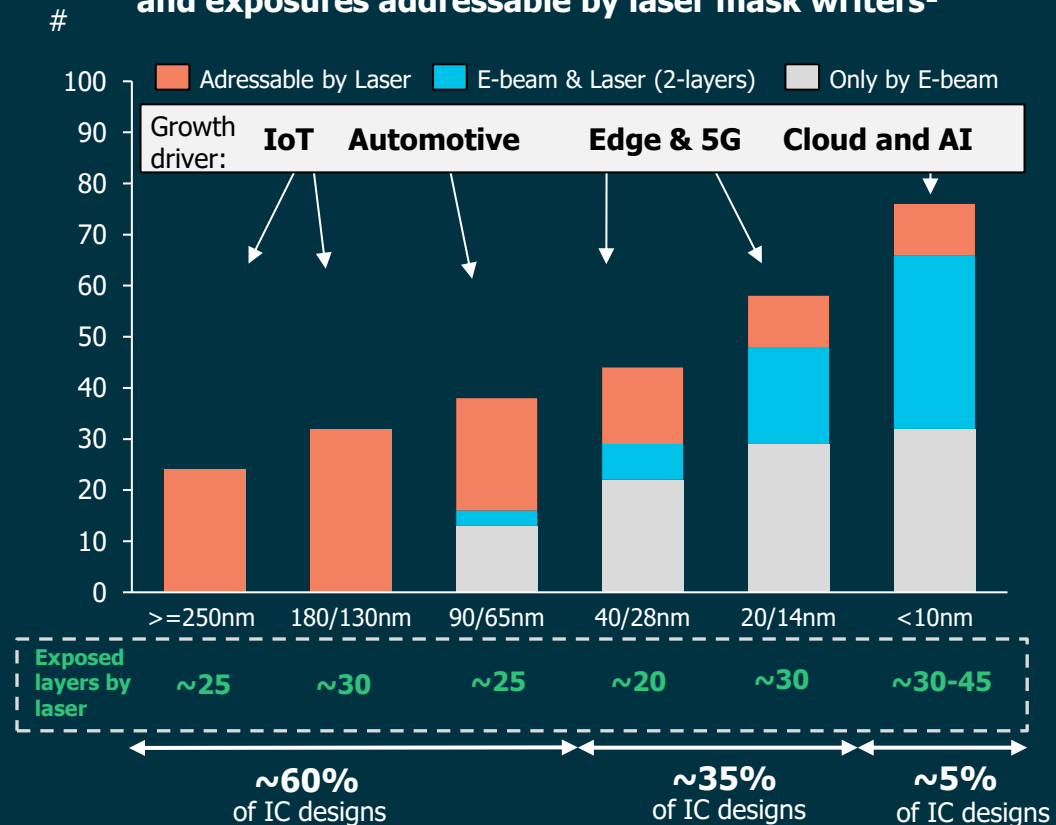


1. TechInsights March 2026

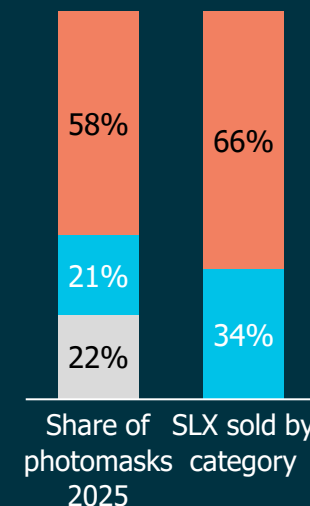
Semicon photomask market trends and our strategy

Laser needs largely node independent, many of the sold SLX tools serve the high-end market

Typical number of masks per design and how many layers and exposures addressable by laser mask writers¹



Total share of photomasks by type, and share of SLX's sold primary for that category²



Focus on serving mature markets, complemented by applications broadly exposed to high-end

1. Mycronic estimates

2. TechInsights January 2026 & Mycronic estimates



Introducing next generation SLX

**Offers increased number of addressable layers and
higher productivity for second-layer writes**

Born to run
Designed for freedom

SLX Kite

The most capable laser writer on the market

First shipment planned for H2 2027

Key highlights

Unprecedented productivity¹

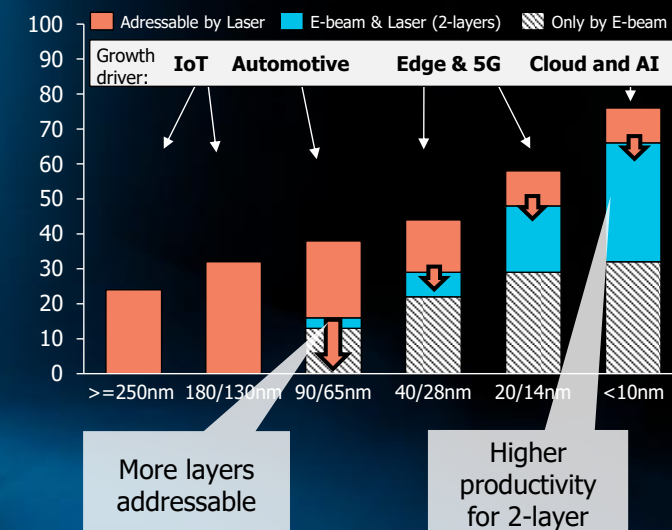
15 → 29 beam optics, deliver up to >80% higher throughput, can be configured by SW

Accuracy to address the growing "low end e-beam market"

Productivity can be traded for accuracy, enabling 65nm node critical layers

"80% increased throughput and capability to address critical layers at 65nm technology node"

Typical number of masks per design and how many layers and exposures addressable by laser mask writers²



1. For equal capability and productivity prices will be similar as first generation SLX
2. Mycronic estimates



INTRODUCING

The new IQX series

Productivity redefined for mainstream inspection

First revenues expected in 2027

**Expanding Pattern
Generators into a new
product and technology
segment, with the long-term
potential to become a
business larger than SLX**

Key highlights

**Lowest
inspection cost
per mask**

**"Superior
inspection speed
and low running
cost"**

**A long term
committed
supplier**

**"Modern, stable
platform built
for future
innovations"**

**With IQX there is
nowhere to hide**

We are well positioned to seize this opportunity, by combining and leveraging our existing technology, deep industry expertise and partner network, with new technology development, to drive innovation and create customer value.

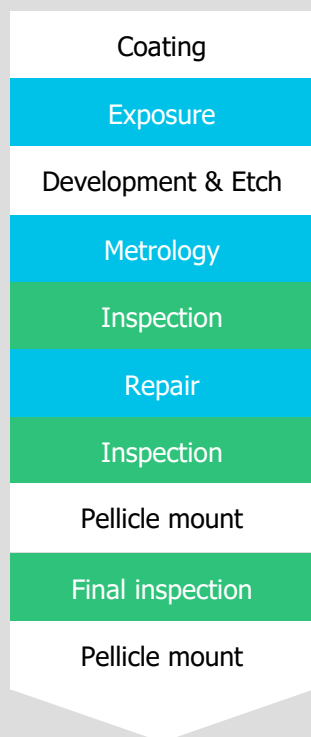


Photomask inspection – what is it?

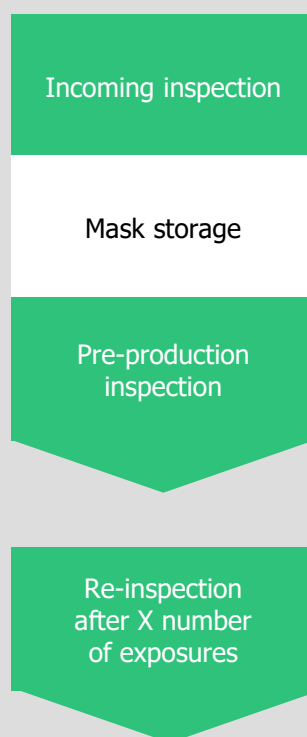
Process step to verify that all patterns are printed as intended and that the mask is free from defects and contamination that could impact production yield

Photomask inspection is done several times in the mask shops, but also in the semicon fabs, estimated to be a USD 1,400 million annual equipment market

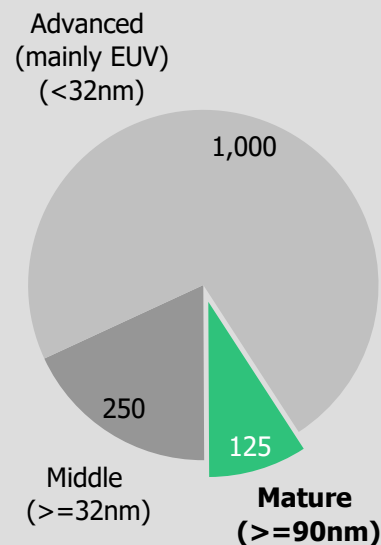
Mask shop



Semicon fab¹



Inspection equipment market² – USD million



1) Inspection steps vary depending on how advanced the fab is and the way of working
2) Mycronic estimate

Process steps addressed by IQX

Process steps covered by other PG products

Inspection demand for mature nodes on the rise

Market opportunity and positioning

- IQX will initially cover critical layers down to the 90 nm node, non-critical layers at smaller nodes as well as particle and contamination for even more advanced nodes
→ IQX addressing >50% of semiconductor mask production
- Growth at mature nodes and an aging installed base are driving replacement demand
- 400 legacy tools expected to be replaced over the next decade
- ~USD 125 million annual addressable market, with tool prices in similar range as SLX depending on configuration, reflecting significantly higher productivity than legacy solutions
- Competing with KLA, Lasertec, and Chinese suppliers
- Ambition is to over time capture >40% of the addressable market

→ **Initially a market opportunity similar to SLX, with semicon fabs opening a new growth avenue, long-term potential to surpass SLX in scale**



COWIN

Founded in
2005

71 employees in
South Korea

Joined March
2026

Within and beyond photomask - Cowin expands capabilities and growth potential

Strategic rationale

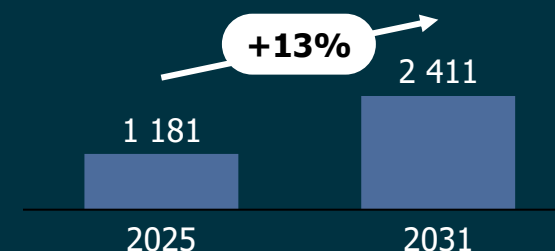
- Display and semiconductor photomask repair products enable connected solutions
- New technologies for wafer inspection and cleaning as well as products for display panel repair
- Mycronic's global operation and larger scale can accelerate Cowin's success in existing and new product lines
- Similar customer base, and access to new markets
- Strengthen exposure to the Korean tech hub
- Strong fit across technologies, capabilities, and culture, for faster innovation
- Additional production facility strengthens resilience

Beyond photomask

– Focus on wafer backend & advanced packaging

Wafer Level Packaging Inspection Equipment

USD million¹



- AI-driven advanced packaging is fueling demand for advanced metrology and inspection to maximize yield and optimize process control
- Cowin has developed a combined inspection, and repair platform which addresses niche applications within this growing market. Since the acquisition, Mycronic has accelerated the development
- The solution is under evaluation by several leading customers, with a long-term strategy to expand through continued innovation and proven Mycronic technologies

1) Techinsight, June, 2026

Cowin WIZ – An entry point to wafer backend & advanced packaging markets

Division **Pattern Generators**

Display photomask – Enabling the display industry

- Incremental development and technology readiness to push high-end
- Trade-in program to support customers through generation shifts

Semiconductor photomask – Broaden and develop our portfolio

- Expanded mask writer portfolio with metrology, inspection, and repair
 - Leverage SLX Kite to accelerate legacy tool replacement including low-end E-beam
 - Establish IQX on the market and extend customer base to include semicon fabs
- Actively develop platforms over time to expand addressable market
- Technology leadership in semiconductor packaging

Beyond Photomask – Primarily address opportunities in advanced packaging

- Leverage existing core technologies for new applications and opportunities
- Accelerate development of wafer inspection and upfront investment in sales and service org



Number one
Patterning Solutions
company in selected
segments

Capital Markets Day 2026

DIVISION

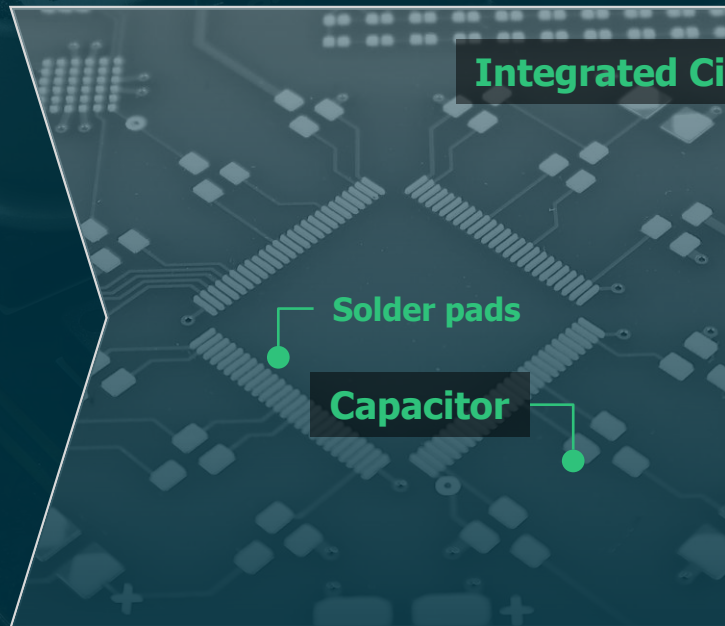
PCB Assembly Solutions

Clemens Jargon

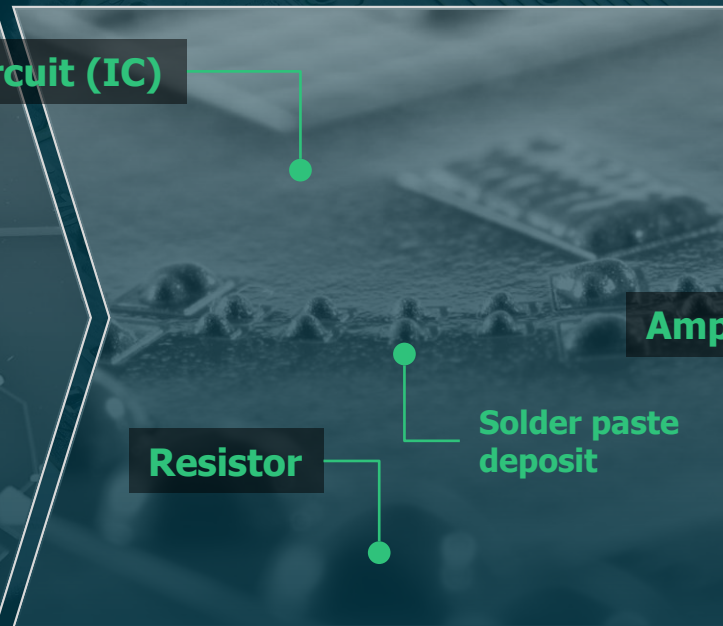
Sr VP PCB Assembly Solutions

The Printed Circuit Board Assembly (PCBA)

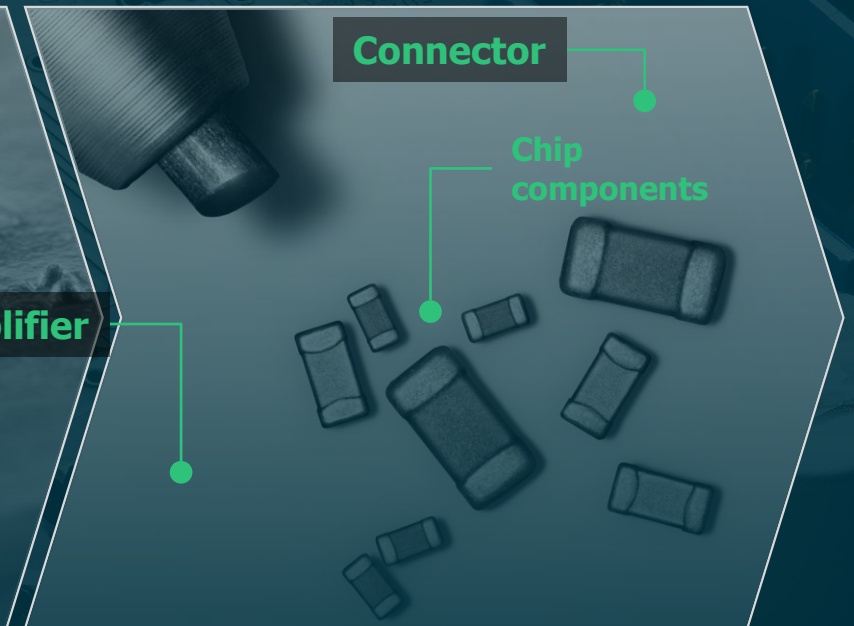
1. Printed Circuit Board (PCB)



2. Solder paste application



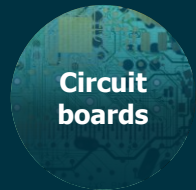
3. Electronics components



Our place in the value chain

Production equipment for assembly of PCBs in electronics manufacturing

Materials



PCB Assembly



Zero defects and highest productivity for
any product mix

Products



Jet printing

What does it do

High-speed, high-accuracy on-the fly dispensing of solder paste and other adhesives on to printed circuit boards.

What does it solve

- High-quality solder joints
- Board revisions on-the-fly
- Zero changeover time between jobs
- Consistent print result over time

Customers

- Electronic manufacturers with frequent job changeovers and new product introductions (NPI).
- High volume manufacturers seeking to solve solder paste dispensing on challenging board designs.



MYPro MY700 – Versatile high-speed jet printing platform

Stencil printing

What does it do

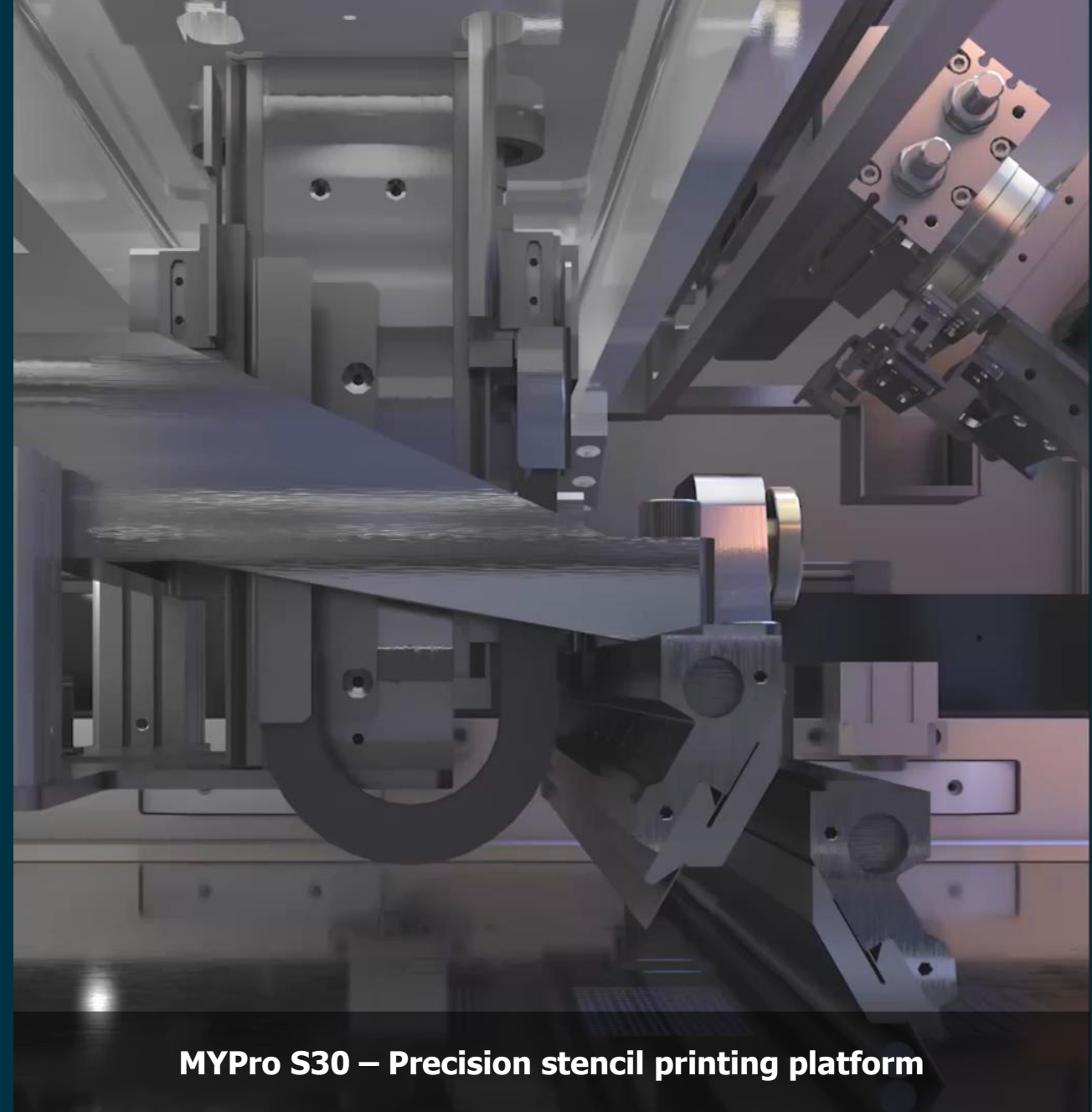
Fast and accurate application of solder paste on to printed circuit boards with a metal stencil.

What does it solve

- Unbeatable cycle time for larger batches and high-volume production lines.
- Accurate print result with closed loop control to SPI.
- Offering both printing speed and solder joint quality when combined with a Jet Printer.

Customers

- High volume manufacturers with a need for shortest cycle (takt) times running larger batches.
- Electronic manufacturers seeking to solve solder paste application for challenging board designs, combining stencil with jet printing technology.



MYPro S30 – Precision stencil printing platform

Solder Paste Inspection

What does it do

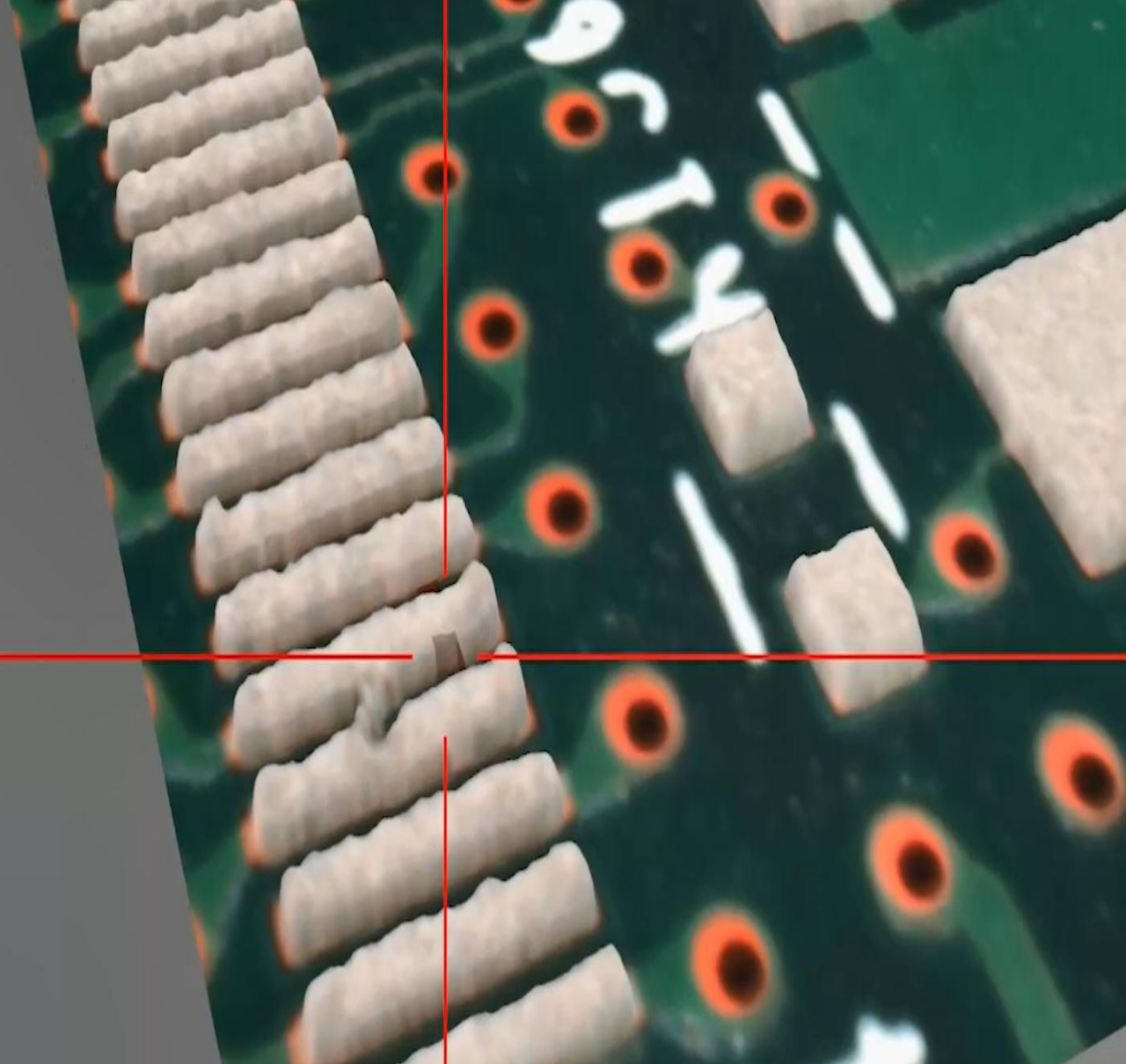
High-precision 3D inspection of the solder paste print pattern on printed circuit boards.

What does it solve

- Eliminates errors
- Accurate and consistent volume measurement
- Auto-programming

Customers

- Manufacturers of high-reliability electronics in segments such as automotive and aerospace.
- Electronic manufacturers with a need to secure yield in PCB assembly.



MYPro PI – Accurate solder paste inspection made simple

Component placement

What does it do

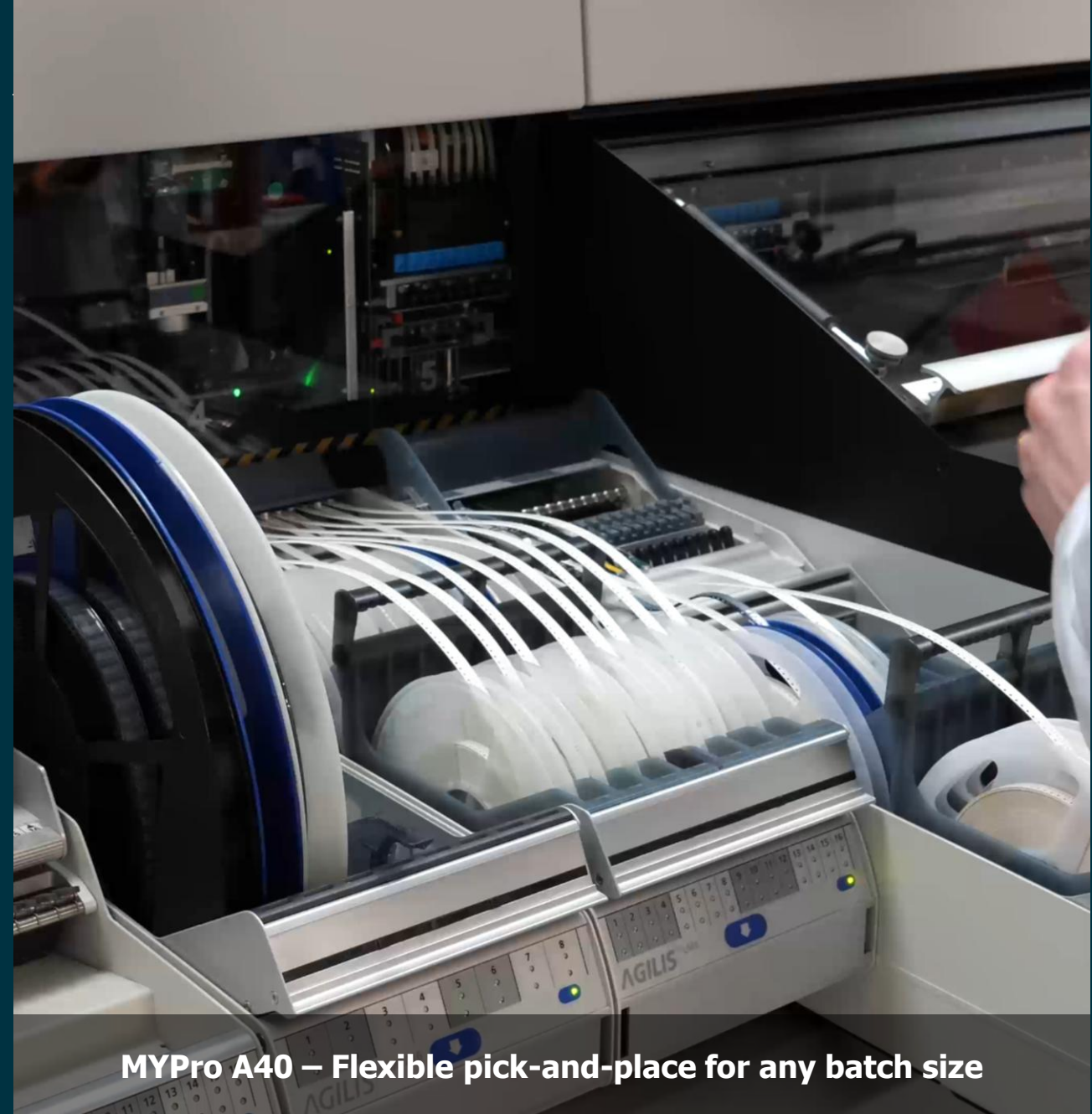
High-accuracy mounting of electronic components on printed circuit boards.

What does it solve

- Mount any component on any board
- All-in-one capability
- Low changeover cost
- High equipment utilization in high-mix
- Efficient production down to batch size one

Customers

- Electronic manufacturers of high-value, high-quality electronics with frequent changeovers and New Product Introductions (NPIs).



MYPro A40 – Flexible pick-and-place for any batch size

Component inspection

What does it do

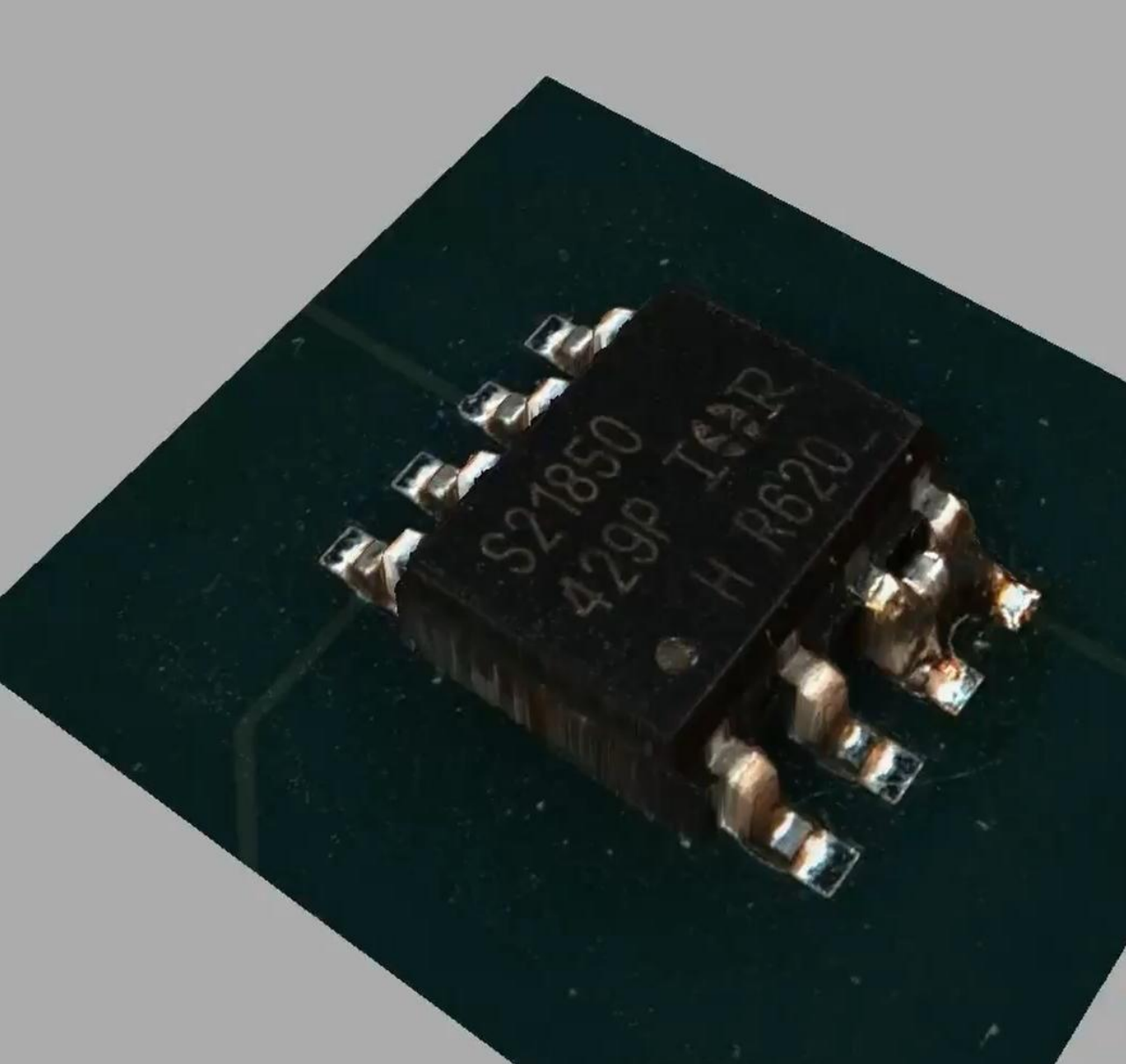
3D inspection of components and solder joints, with a comprehensive defect coverage on assembled printed circuit boards before or after the reflow oven.

What does it solve

- Secures production quality
- Improves first pass yield
- Identifies process issues
- Robust and easy programming supported by AI

Customers

- Electronics manufacturers with high-quality requirements, e.g. manufacturers of high-reliability electronics in segments such as automotive and aerospace.



MYPro I50/I51 - Put your inspection on autopilot

Material storage

What does it do

Automated and safe storage of electronics components on reels.

What does it solve

- Improves production efficiency
- Automates the material flow to and from the line
- Reduces risk of misplaced components in factory
- Controlled environment for sensitive components

Customers

- Volume manufacturers looking for an automated buffer storage solution near the production lines.
- Small to mid-sized electronics manufacturers in need of an intelligent material handling solution for the most frequently used parts.



MYTower – Intelligent and safe storage of components

Reach new levels in agile assembly with MYPro Line™

Factory connectivity

Implement the IPC-CFX standard effortlessly with MYPro Connect™, or deploy the Hermes M2M communication protocol across your Mycronic line.

MYPro Create™

One dataset. One program. One workflow. Import data once to create one program for all Mycronic jet printing and inspection machines. Eliminate repetitive tasks with one software for a single intuitive workflow.

MYPro A™ series pick-and-place

Turn up the volume - high speed meets high flexibility. With the new MYPro A41 now supporting PCBs up to 1000 x 609 mm, the range becomes even more versatile.

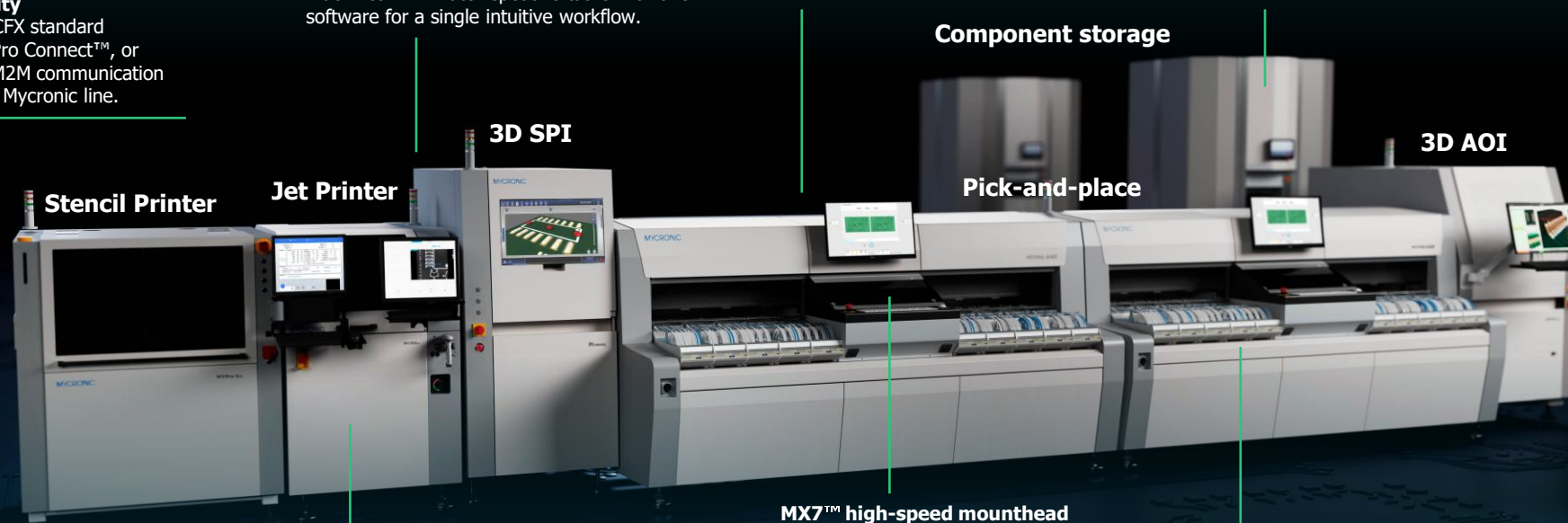
Automated material handling

Experience the industry benchmark for speed of material handling, ease of use and storage capacity: MYTower™ storage systems and supporting software solutions.

Component storage

GenI™ - Generative inspection

The first of its kind to autonomously create production-ready 3D AOI inspection programs based solely on pick-and place and initial 3D AOI scan data.



Process optimization

MYCenter Analysis™ is a powerful process control software to monitor, analyze and improve assembly performance.

Fine-pitch ejector

Mycronic's latest jet printing innovation delivers solder paste dots as small as 180 µm, enabling precise, stencil-free printing for fine-pitch and cavity applications.

MX7™ high-speed mounthead

A modular high-speed mounthead with seven independent placement nozzles. Consisting of 14 individual Z and theta motors enabling placement of 99% of all components.

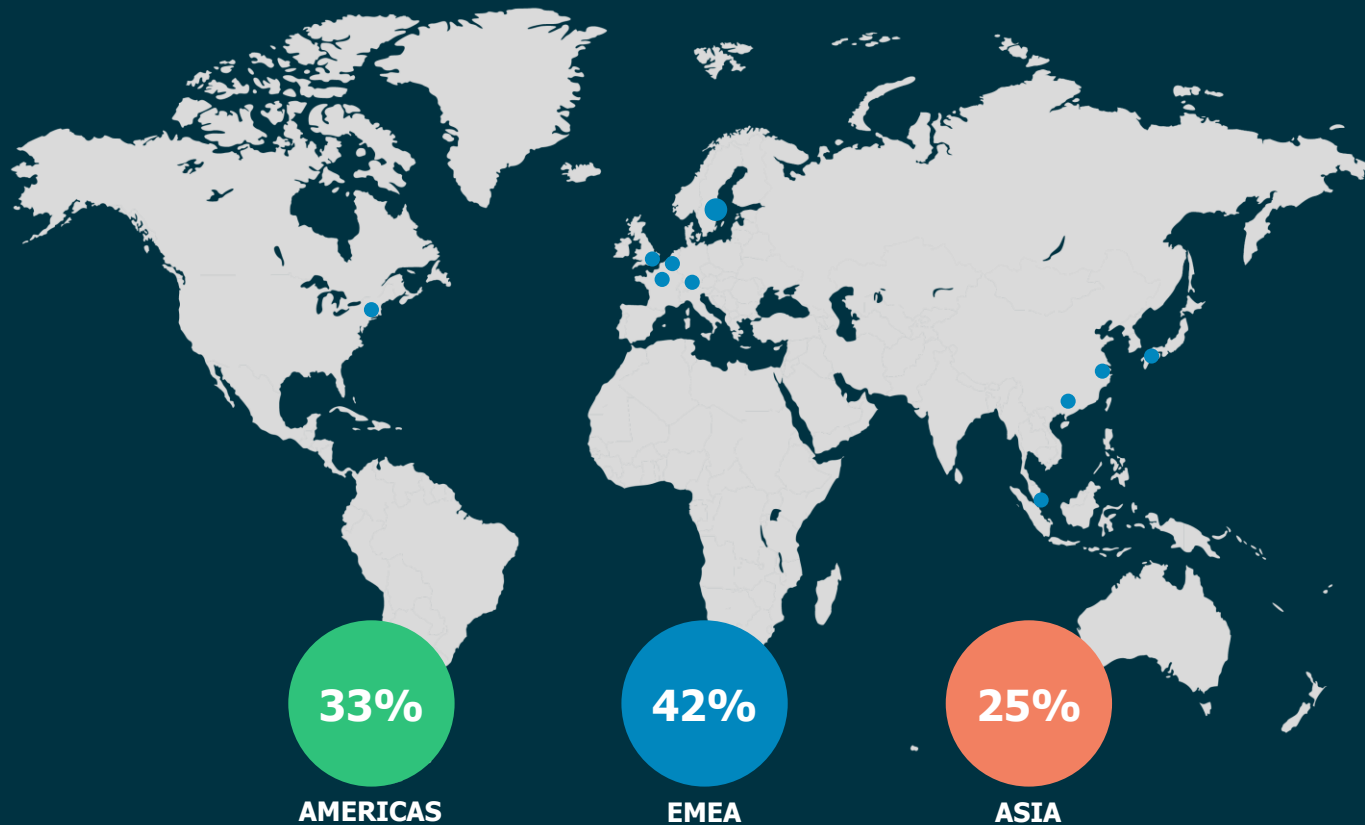
Agilis™ feeder system

A redesigned 8 mm feeder. A more user-friendly "all-reel-size" Agilis Flex feeder. And a new Agilis bin for 15" reels. The icon of agility keeps shortening your changeover time.

Escape Tracker™

Eliminate escapes. Reduce false calls. And automatically add new levels of speed and reliability to inspection programming.

Worldwide **footprint** 2025



Revenue share by region in 2025.

More than 50 years
of experience in innovation

Mycronic PCB AS is represented
in more than 50 countries

More than 7,500 production systems
at more than 2,700 customers

A global organization with
493 employees in 10 countries

5 R&D centers
in Sweden, France, Japan, Czechia and China

The power of innovation
is proven by more than 100 patents

Our market

- Mycronic has a strong market position within high-mix electronics manufacturing, where product changeovers are frequent.
- Mycronic has a unique full-line offering of flexible production equipment, process control software and software tools for factory connectivity.
- Mycronic production lines are common where high-value PCBs are built for industrial, aerospace/defense, medical, space and automotive applications.
- The equipment market is competitive, with several larger global equipment suppliers targeting the PCB assembly market.
- The electronic systems market has a long-term growth forecast – expect a stable market for electronics assembly equipment.

Market drivers

- Agile production
- Factory automation
- Miniaturization
- AI modules

Our customers

Core customer group: Electronics manufacturers of PCB assemblies, EMSs and OEMs, primarily in Europe and North America in need of **flexible production solutions** combining capabilities

- Mount any component on any board
- Zero changeover time in high-mix environments
- Zero defects
- Highest first pass yield

In addition: Leading global electronics manufacturers looking for **unique process capabilities** and **technologies** to

- Achieve high-quality solder joints
- Automate material handling
- Improve process control
- Ruggedize electronics



QUALITY

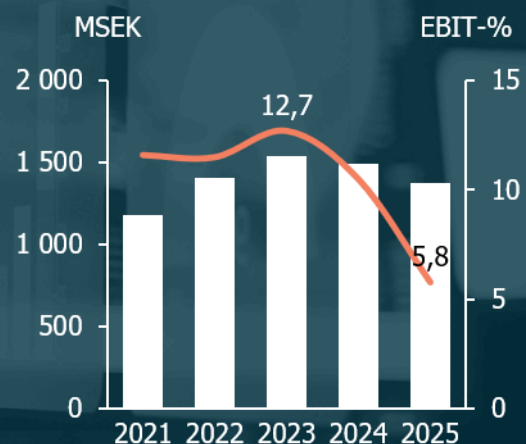


PRODUCTIVITY



FLEXIBILITY

Division PCB Assembly Solutions



Target 2027

>10%

**EBIT margin, reached
before the end of 2027**

Profitability improvement
program initiated. Cost
estimated at SEK 100 million.

Key activities for profitability

- Improving product gross margins
- Strengthening product and business mix
- Optimizing the organization for the future
- Automating and simplifying work processes

Division **PCB Assembly Solutions**

Focus areas

- Broaden aftermarket – accelerating customers to success
- Grow within home turf
- Extend business into new markets



Sustainable profitability



Number one
high flex solutions
provider for PCB
Assembly

Capital Markets Day 2026

DIVISION

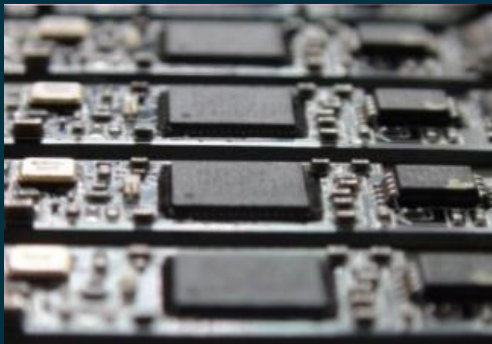
High Volume

Expand core and
develop beyond dispensing

High Volume division principal target industries

Full potential development across different industries

PCBA



Consolidate local leader position and grow overseas in dispensing

Automotive



Capitalize on the electrification trend beyond dispensing

Semiconductor



Offer products into several attractive segments

Final Assembly

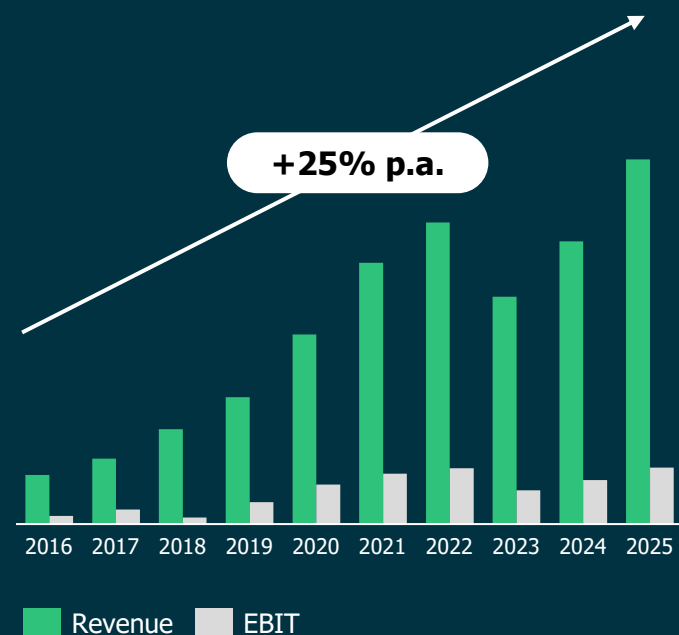


Globally develop module and final assembly automation solutions

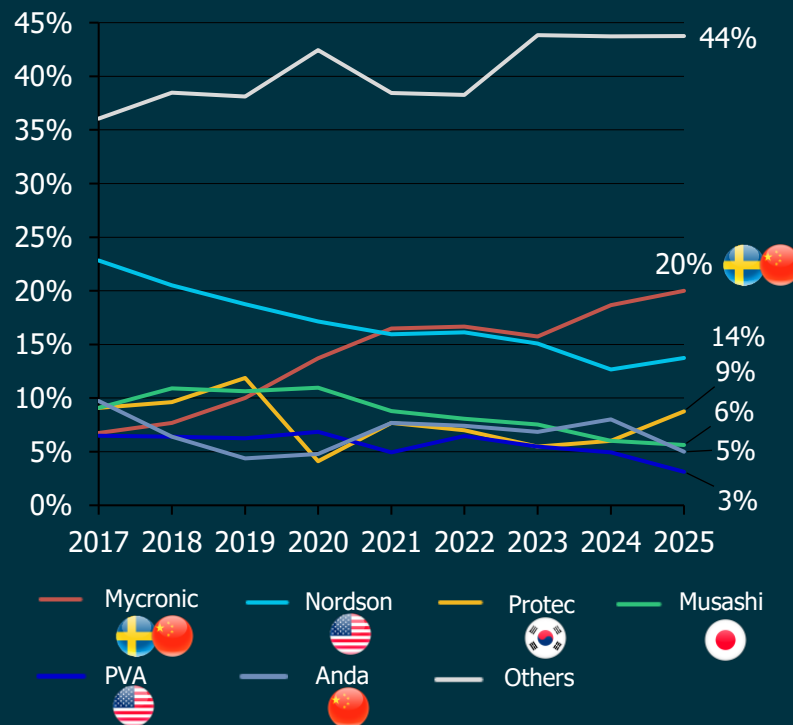
High Volume revenue and market share expansion

Ensure dispensing market leader position

Division revenue growth >25% CAGR

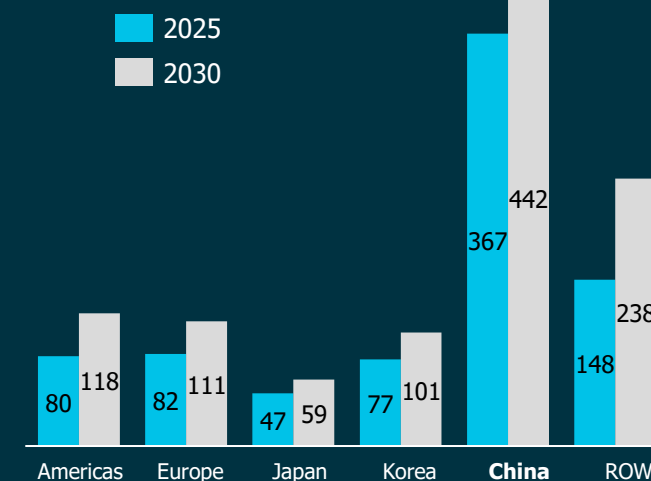


Market shares electronics dispensing



Electronics dispensing market growth

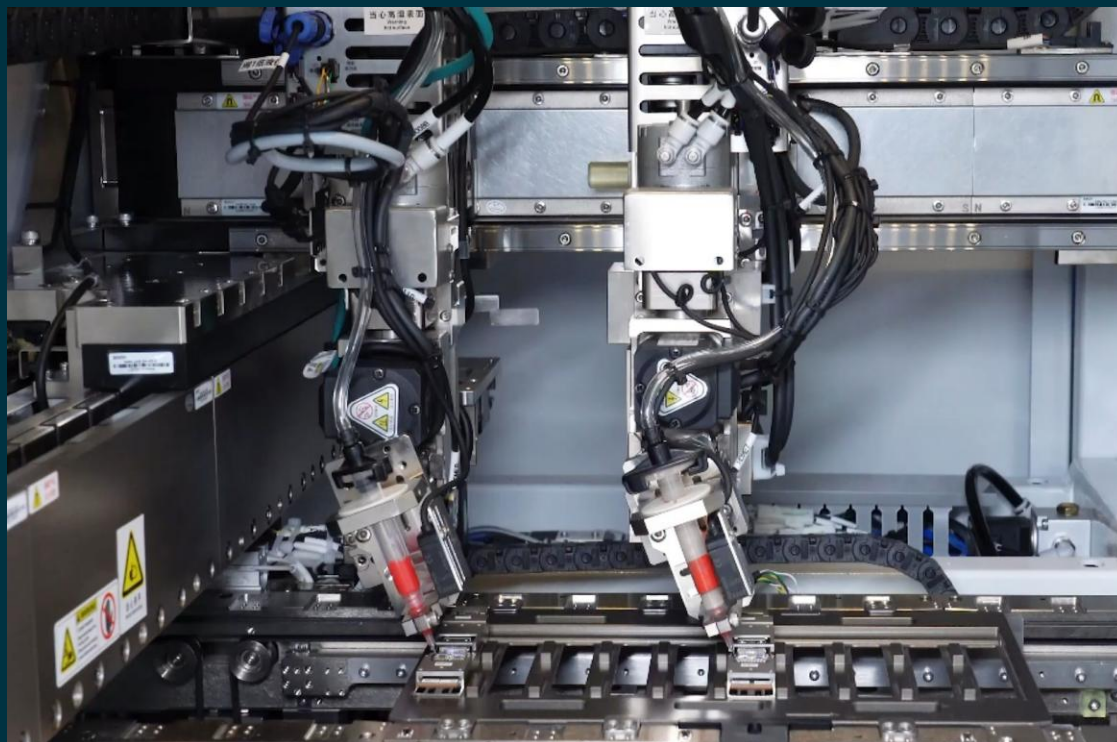
USD 1,070 million in 2030



Source: Prismark April 2026

Core dispensing business expansion

Consolidate leader position and expand market in target industries



Valve

<0.1mm line width
Long lifetime
Stable performance

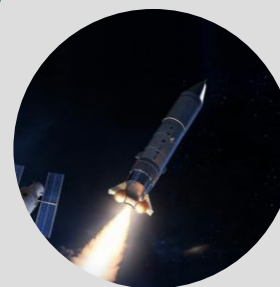
Platform

3m/s speed
3G acceleration
0.01mm accuracy
Modulization

Software

Flexible and robust
axxon vision ®
Deep learning

Faster! Sharper! Smarter!
New target industries



Aerospace



Medical



AI infrastructure

Product portfolio expansion

Expand application based on existing unique technology



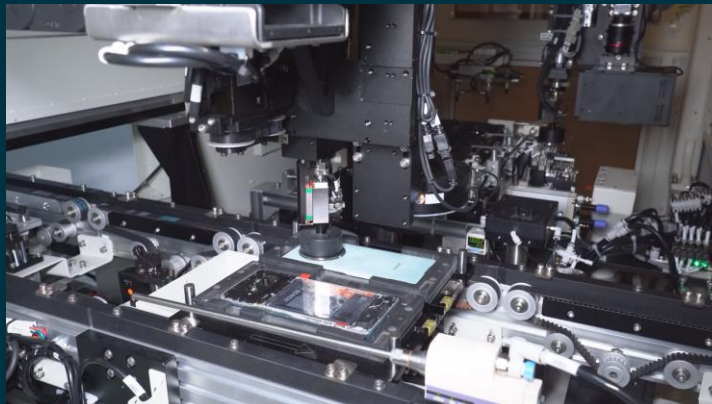
Standard 5-axis dispensing



Upper 5-axis dispensing



5-axis glue clean



5-axis tilt attachment

1

Unique technology, validated for dispensing applications, with strong high-volume business potential

2

Customer and industry for new solution is overlapped with dispensing application

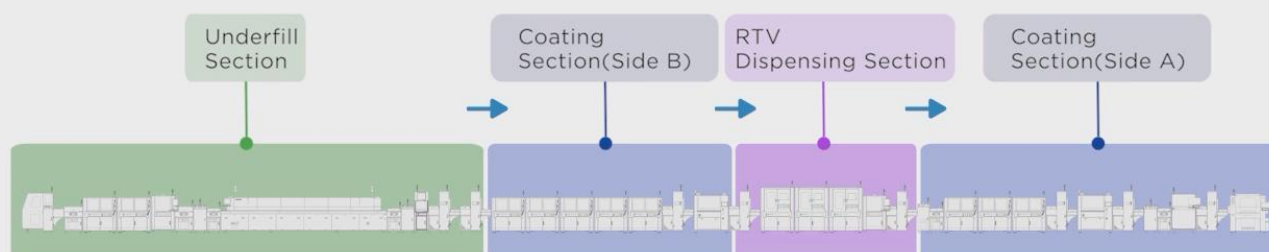
3

Enhance platform functions and flexibility, including path auto-generation, 3D inspection and fiducial mark capabilities, to boost competitiveness

Product portfolio expansion

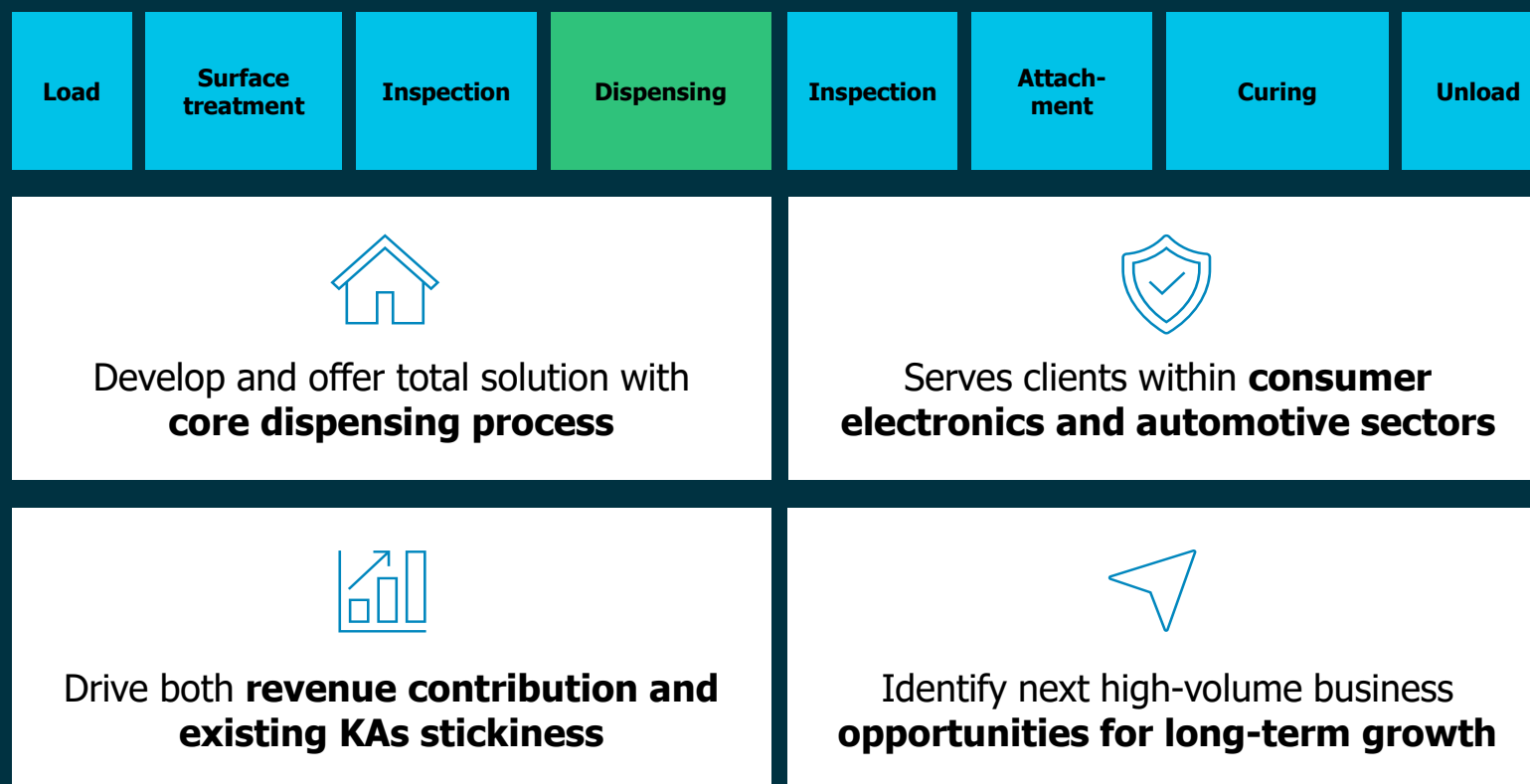
Expand application based on core dispensing

Intelligent Driving **Control Board** Assembly Line



Product portfolio expansion

Expand application based on core dispensing



Product portfolio expansion

Expand application based on new hot opportunity

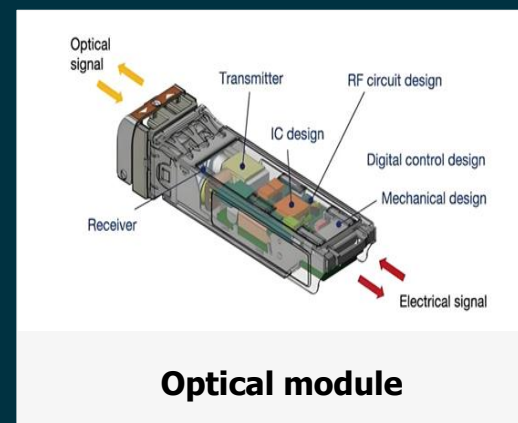


Overlap
existing
customer
and
technology

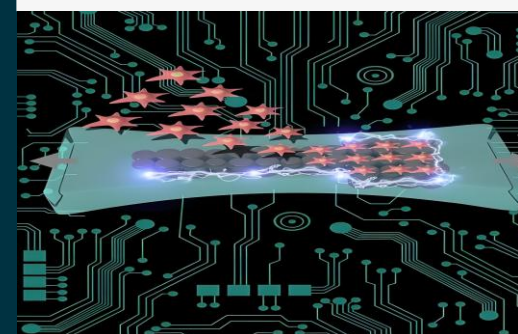
High
technical
threshold
and good
profitability

High volume
business
opportunity

Market
tendency in
electronics



Next generation solar panel



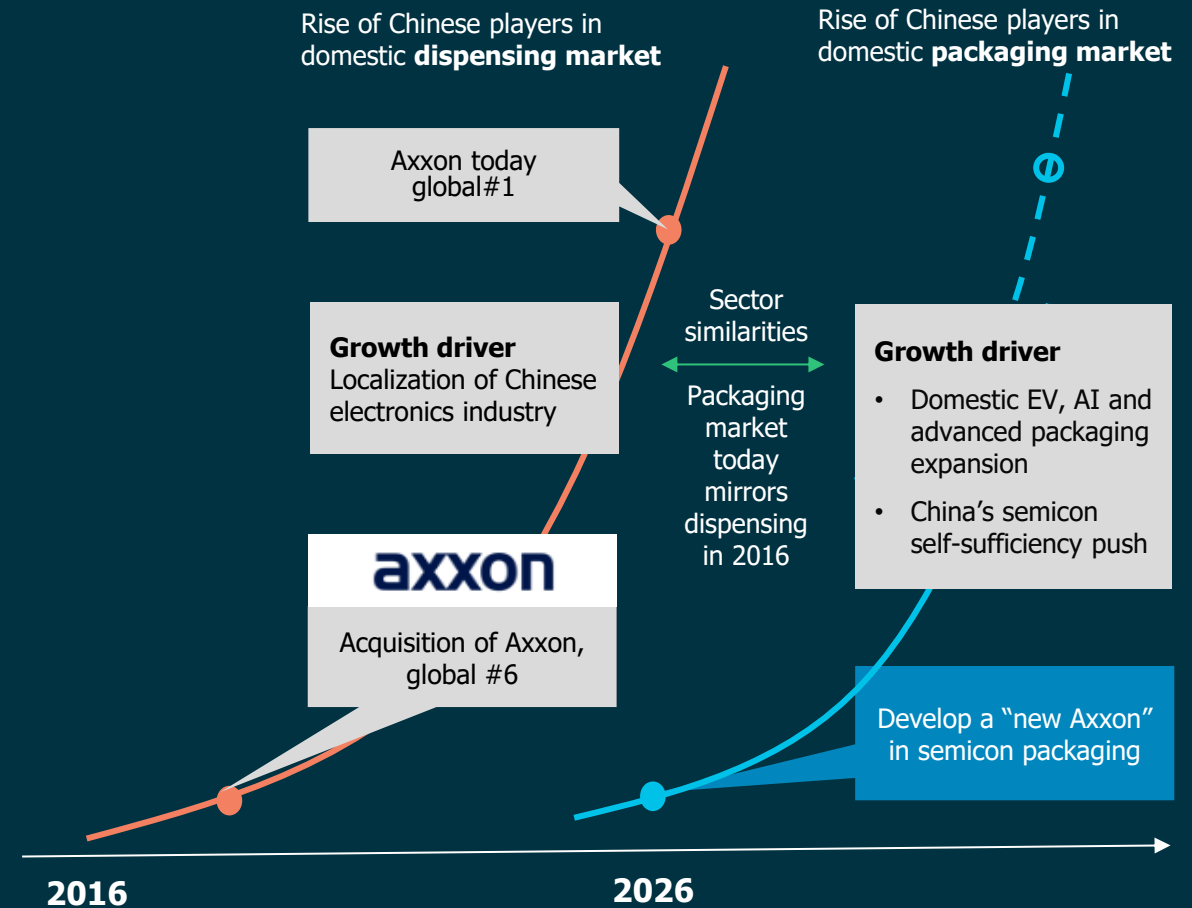
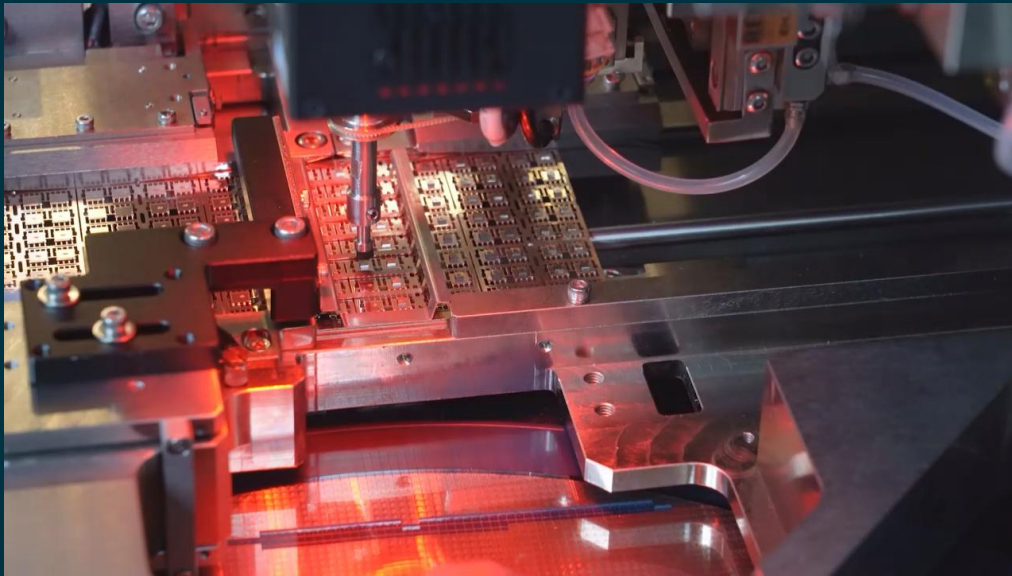
3D circuit print



Digital inkjet

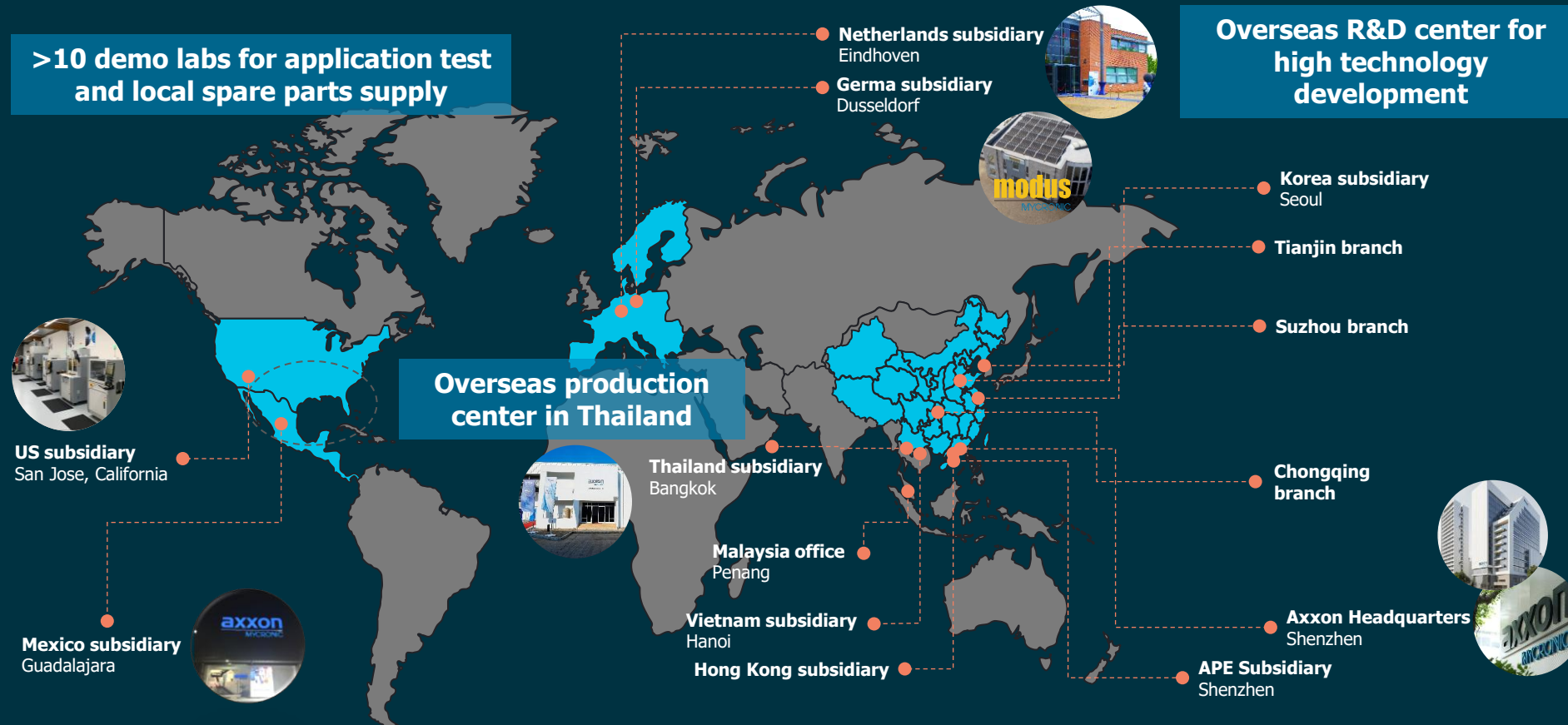
Product portfolio expansion

Expand product based on long-term ambitious target



Global expansion and operational resilience

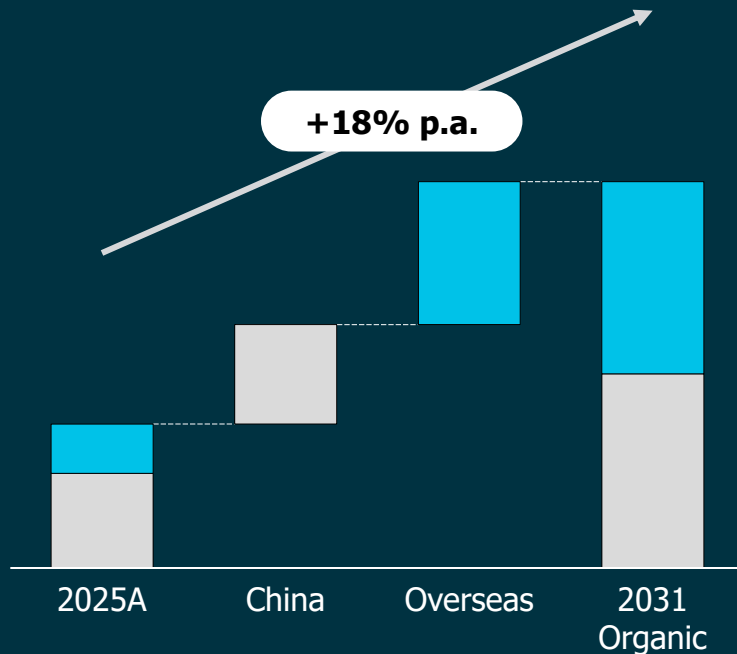
Powerful global sales/service capabilities across all target global regions



Overseas markets – target 50% of revenue

Overseas to contribute 50% of revenues in next 5 years, with good profitability

Organic revenue growth by region



Domestic

Searching for the second growth curve

South China

- Expand to FATP
- New application promotion

East China

- Local tier-1 / Aerospace
- Semicon & Optical modules

Distributor/North/West China

- Developing state-owned KA base
- Insulated-Gate Bipolar Transistor(IGBT)/Semicon

Overseas

Improve market share with unique position



North America

- Aerospace /Automotive

EMEA

- Tier-1 focus
- Coating-industry dispensing

SEA

- Semicon/Automotive
- India/Indonesia market

Korea

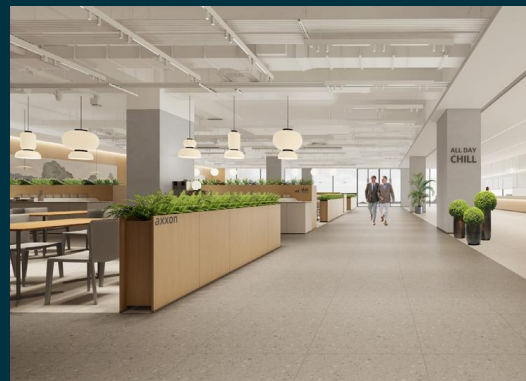
- Duplicate Chinese business
- Expand to automation

New facility supports our ambitions

Groundbreaking in July 2026, ready in Q1 2028

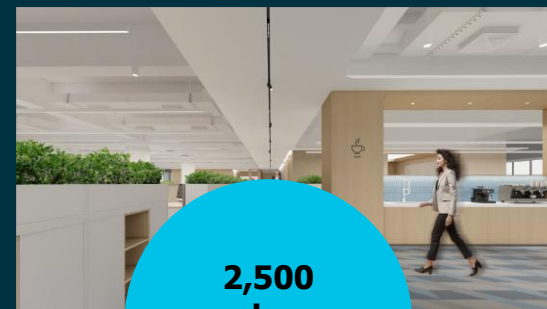
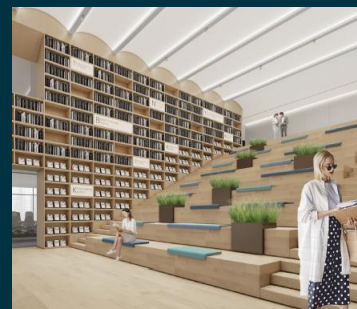
85,000 m²

Total building area



15,000 sets

Annual
production
capability



**2,500
employees**

Work and live

**USD 500
million**

Supported
output value

Division **High Volume**

- Dispensing – consolidate local leadership and expand overseas
- Automotive – capitalize on the electrification trend
- Grow overseas markets – target 50% of revenues
- Semiconductor – offer products into several attractive segments
- Next wave of profitable growth – Long term motivation and M&A



Number one high volume assembly solutions provider for electronics production with core in dispensing

Capital Markets Day 2026

DIVISION

Global Technologies

Magnus Marthinsson
Sr VP Global Technologies

DIVISION

Global Technologies (GT)

Global Technologies is Mycronic's incubator for identifying attractive niches, acquiring future market leaders, and accelerating their growth into successful standalone divisions

Customers

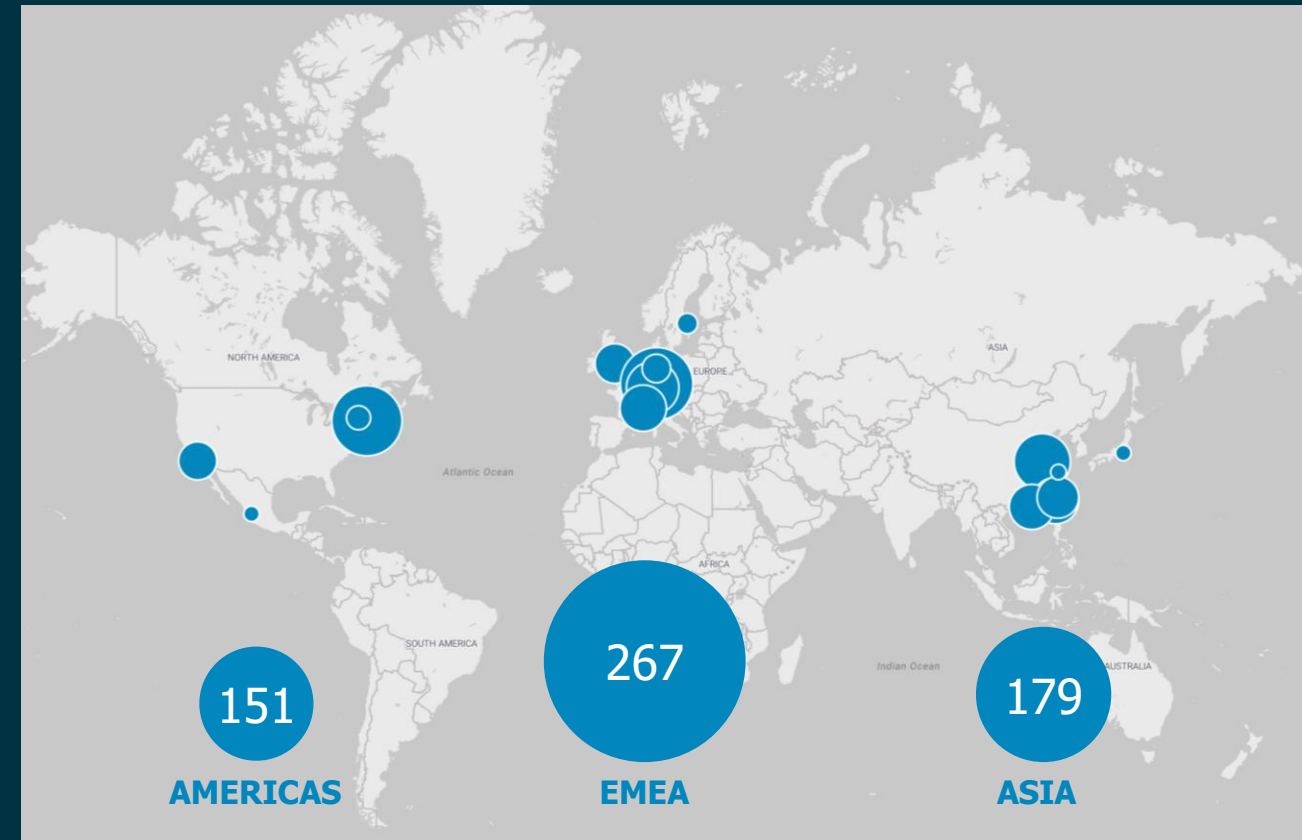
Leading semiconductor manufacturers (IDMs¹), foundries, and OSATs²), PCB manufacturers, photonics and optical communications companies, aerospace & defense suppliers, and research institutions

Organization

>500 employees

Geographical presence

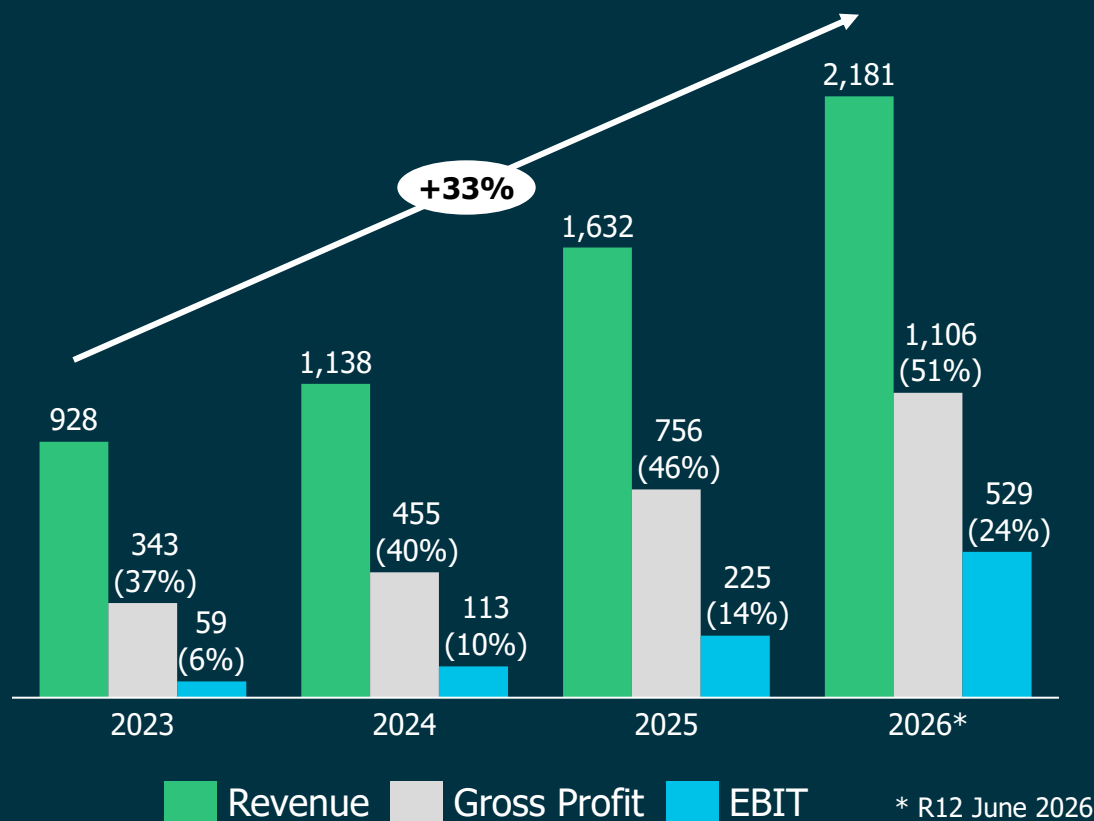
Asia, Europe and the Americas



GT's headcount world map

1) IDM = Integrated Device Manufacturer
2) OSAT = Outsourced Semiconductor Assembly and Test

Business development for Global Technologies (MSEK)



GT's growth journey – organic and acquired growth

2023

- Efficiency program initiated at MRSI

2024

- Vanguard Automation acquired
- Build-out of AI data centers started

2025

- New site for atg in Germany
- Hprobe, RoBAT, and Surfx acquired

2026

- ETZ acquired
- New site for MRSI in China
- New site for Surfx in Taiwan (in progress)
- Production expansion for atg in Germany (in progress)

Summary

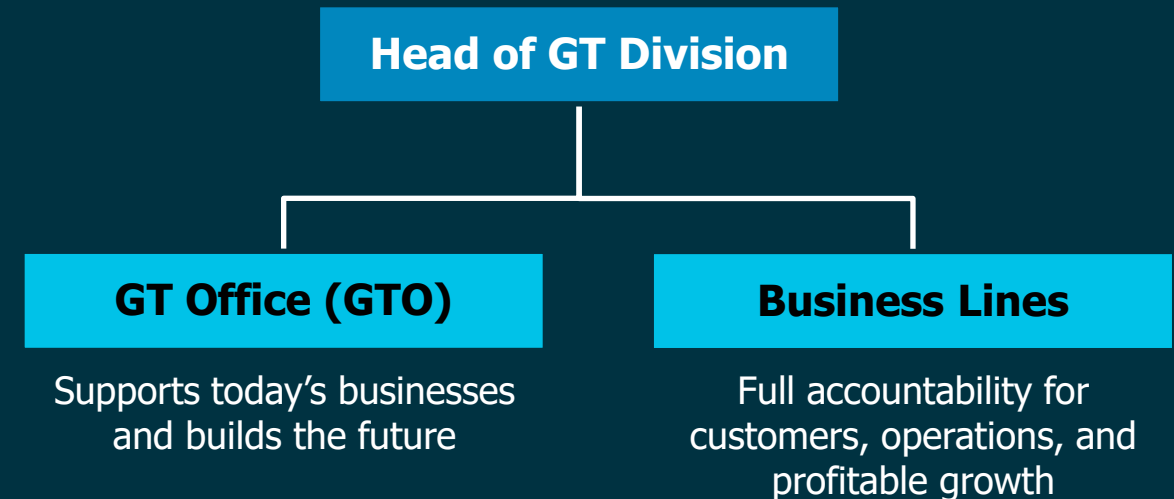
- Stability → profitability → growth
- ~2/3 of the growth has been organic
- Acquisitions expected to contribute to future growth

Global Technologies' operating model

Small-company speed and agility with the strength of Mycronic

- **Decentralized business lines** with full accountability and close customer focus, serving attractive niche markets
- **Small-company speed and agility** combined with Mycronic's global reach, financial strength, and capabilities
- **GT office supports** the business lines and **drives the future growth** through strategy, M&A, technology, and shared capabilities
- Focus on technology leadership, **profitable growth**, and long-term value creation
- Business lines can become **standalone divisions** when they reach sufficient size and maturity

Enabling today's businesses and building tomorrow's growth platforms



Mycronic's M&A deal strategy

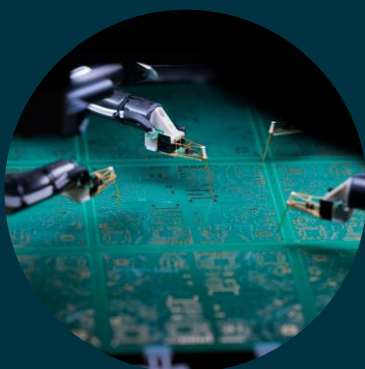
Target segmentation



DIVISION

Global Technologies

PCB Test

**atg**

Market leader in Flying Probe Test solutions for the bare board PCB segment

atg
MYCRONIC

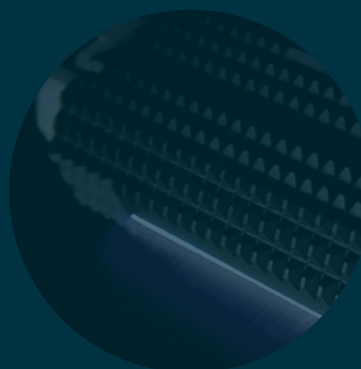
Die Bonding

**MRSI**

Leading provider of high precision die bonding, fluid dispensing, and active alignment solutions

MRSI
MYCRONIC

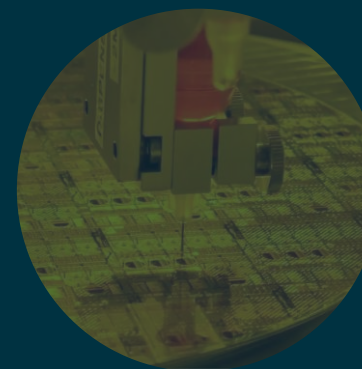
Applied Plasma

**Surfx**

Leading provider of surface cleaning and activation using atmospheric plasma

Surfx
MYCRONIC

Photonic Interconnects



Vanguard Automation
Technology leader for photonic packaging using 3D laser nano-printing

vanguard
AUTOMATION
MYCRONIC

Magnetic Test

**Hprobe**

Technology leader in the emerging niche market of MRAM testing in Tier-1 foundries

Hprobe
MYCRONIC

PCB Test

Enabling high-speed electronics through PCB testing

What it does

Electrical test solutions for high-end PCBs and substrates

Technologies

- **Flying Probe Test (FPT)** by atg: Verifies electrical connectivity in PCBs and substrates
- **Time Domain Reflectometry (TDR)** by RoBAT: Measures signal integrity in high-speed interconnects
- TDR testing complements atg's proprietary **back drill** test

Why it matters

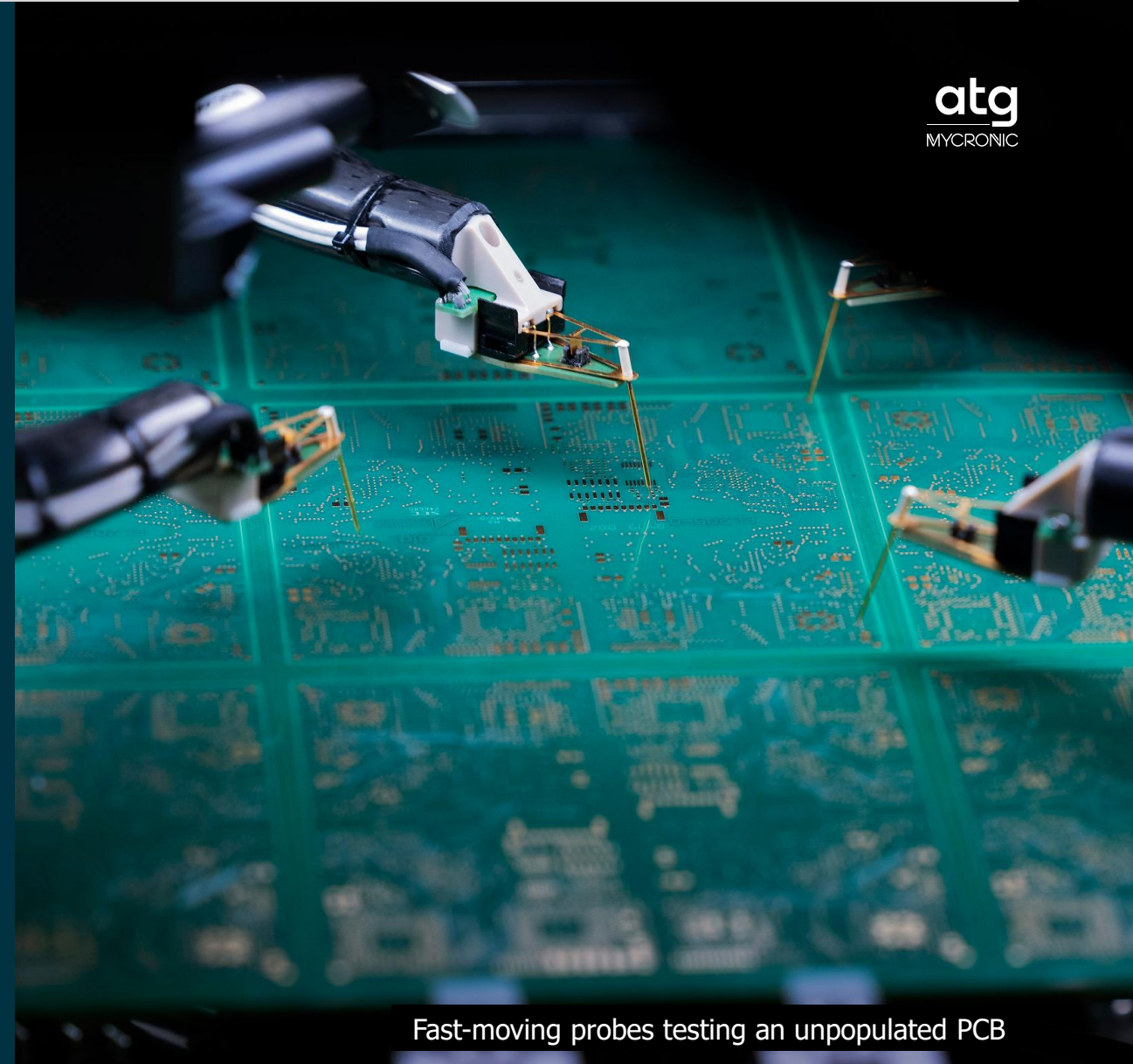
- Detects defects before expensive semiconductor devices are attached

Customers

- PCB and substrate manufacturers for high-end electronics, including AI data centers

Market drivers

- Build-out of **AI infrastructure** and hyperscale data centers
- Increasing data rates and complexity of PCBs and substrates



Fast-moving probes testing an unpopulated PCB

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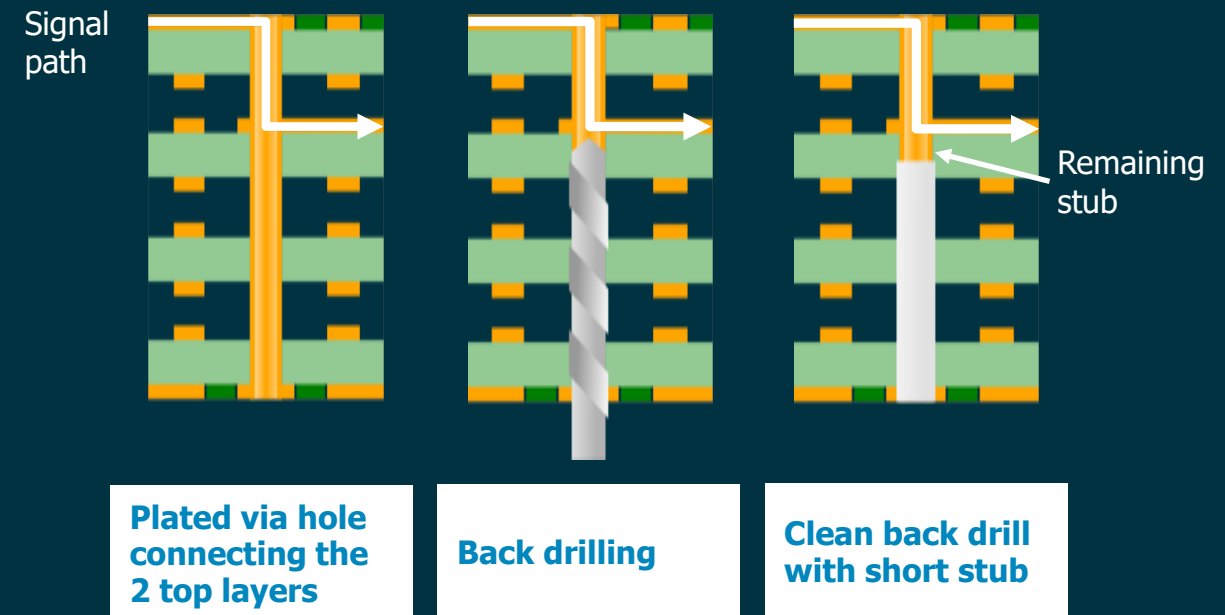
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Back drill visualization

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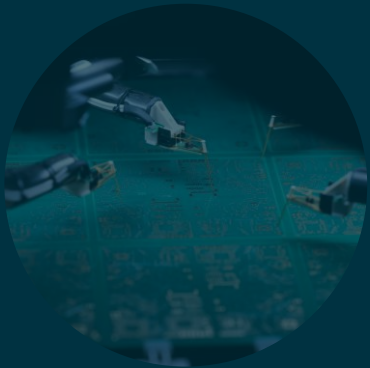


atg Automated Flying Probe Test system A9a

DIVISION

Global Technologies

PCB Test

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atg
MYCRONIC

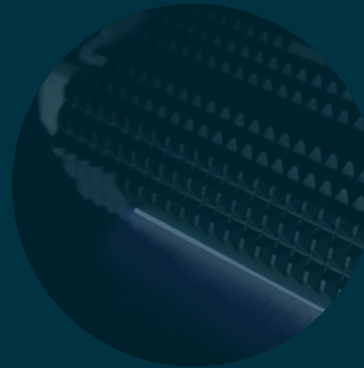
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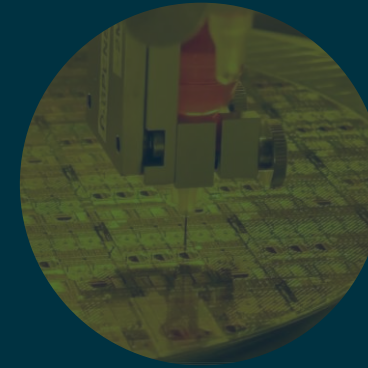
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vanguard
AUTOMATION
MYCRONIC

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Hprobe
MYCRONIC



Die Bonding

Enabling photonic and semiconductor packaging

What it does

High-precision assembly and bonding solutions for advanced photonic and semiconductor devices

Platforms

- **Die bonders:** pick, place, and bond dies onto substrates
- **Dispensers:** apply bonding materials with high precision
- **Active aligners:** align and bond optical components using real-time signal feedback to maximize performance

Why it matters

- Handling of extremely delicate and tiny dies and bonding them at high precision in a long-term reliable way

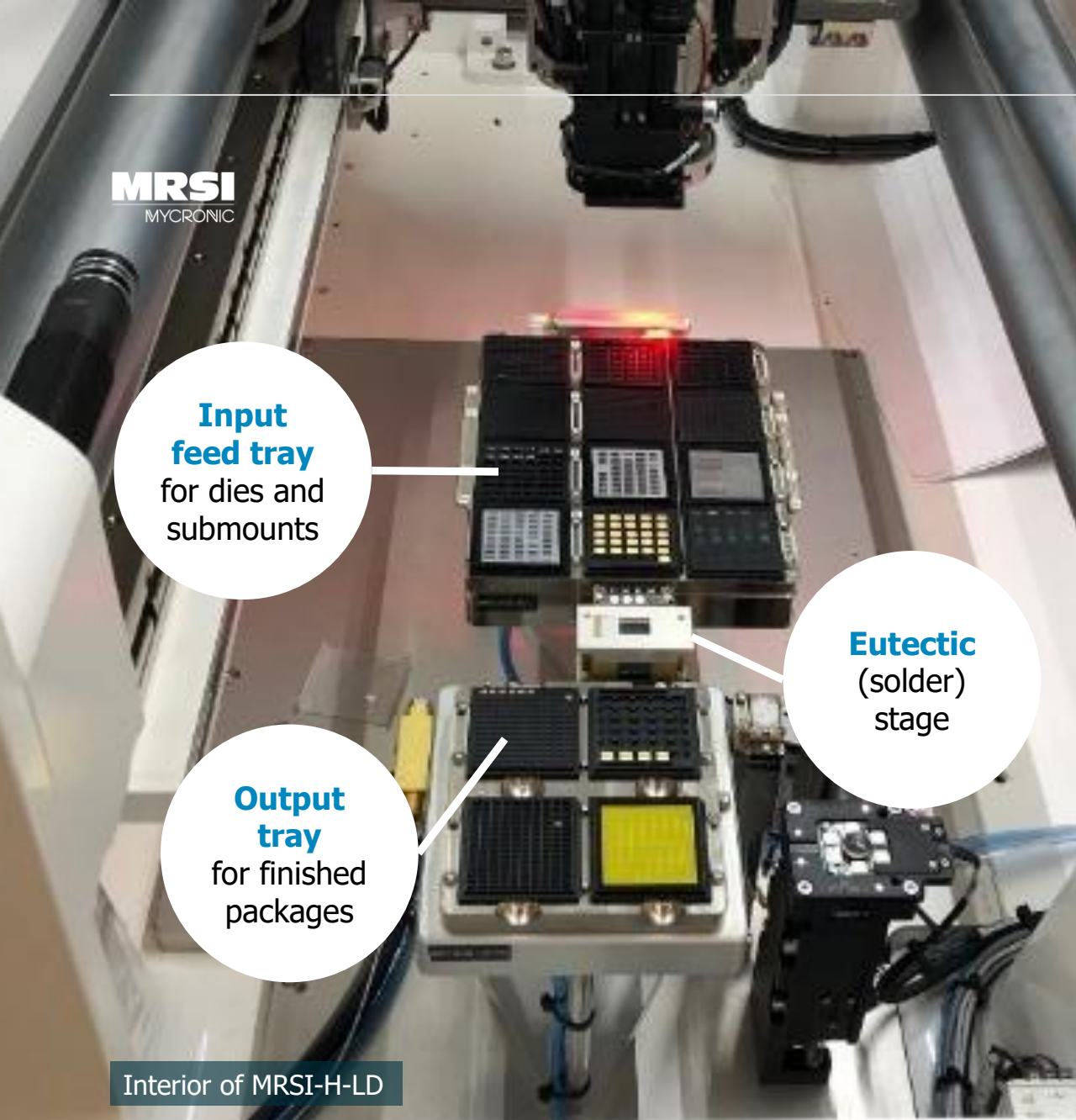
Customers

- Leading optical transceiver manufacturers
- Aerospace & defense suppliers

Market drivers

- **AI-driven** optical interconnect demand
- Aerospace & defense modernization

Dies on wafer

A detailed view of the interior of an MRSI-H-LD die bonding machine. The machine is a complex assembly with various components, including a central processing unit with a red light, and several trays for holding dies and submounts. The machine is designed for high-precision assembly and bonding of advanced photonic and semiconductor devices.

MRSI
MYCRONIC

**Input
feed tray**
for dies and
submounts

**Eutectic
(solder)
stage**

**Output
tray**
for finished
packages

Interior of MRSI-H-LD

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Active aligner MRSI-A-L



1.5 Micron die bonder MRSI-H-LD

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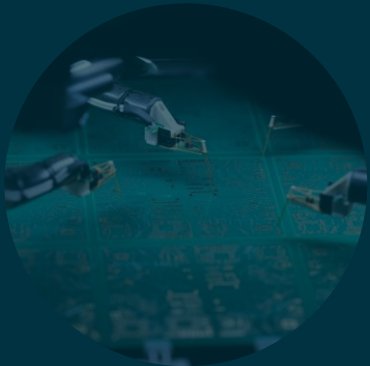
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MRSI
MYCRONIC

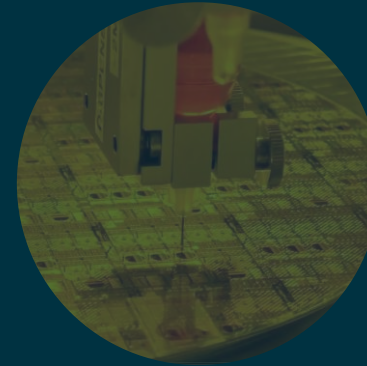
Applied Plasma

**Surfx**

Leading provider of surface cleaning and activation using atmospheric plasma

Surfx
MYCRONIC

Photonic Interconnects



Vanguard Automation
Technology leader for photonic packaging using 3D laser nano-printing

vanguard
AUTOMATION
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Magnetic Test

**Hprobe**

Technology leader in the emerging niche market of MRAM testing in Tier-1 foundries

Hprobe
MYCRONIC

Applied Plasma

Enabling next-generation advanced packaging

What it does

Surface cleaning and activation using atmospheric plasma for advanced semiconductor packaging

Technology

- Uses plasma generated reactive radicals (e.g. H atoms) to remove oxides and contaminants from metal surfaces, leaving water as the only residue

Why it matters

- Improves yield and interconnect performance by removing metal oxide and particles before bonding
- Enables inline processing without batch steps needed for vacuum plasma

Customers

- Leading semiconductor manufacturers in logic and memory

Market drivers

- Growth of **AI data centers** and high-bandwidth memory (HBM)
- Transition toward fluxless thermocompression bonding (TCB) and hybrid bonding



SPS-100 linear beam plasma source

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Copper surface cleaning by Surfx plasma source

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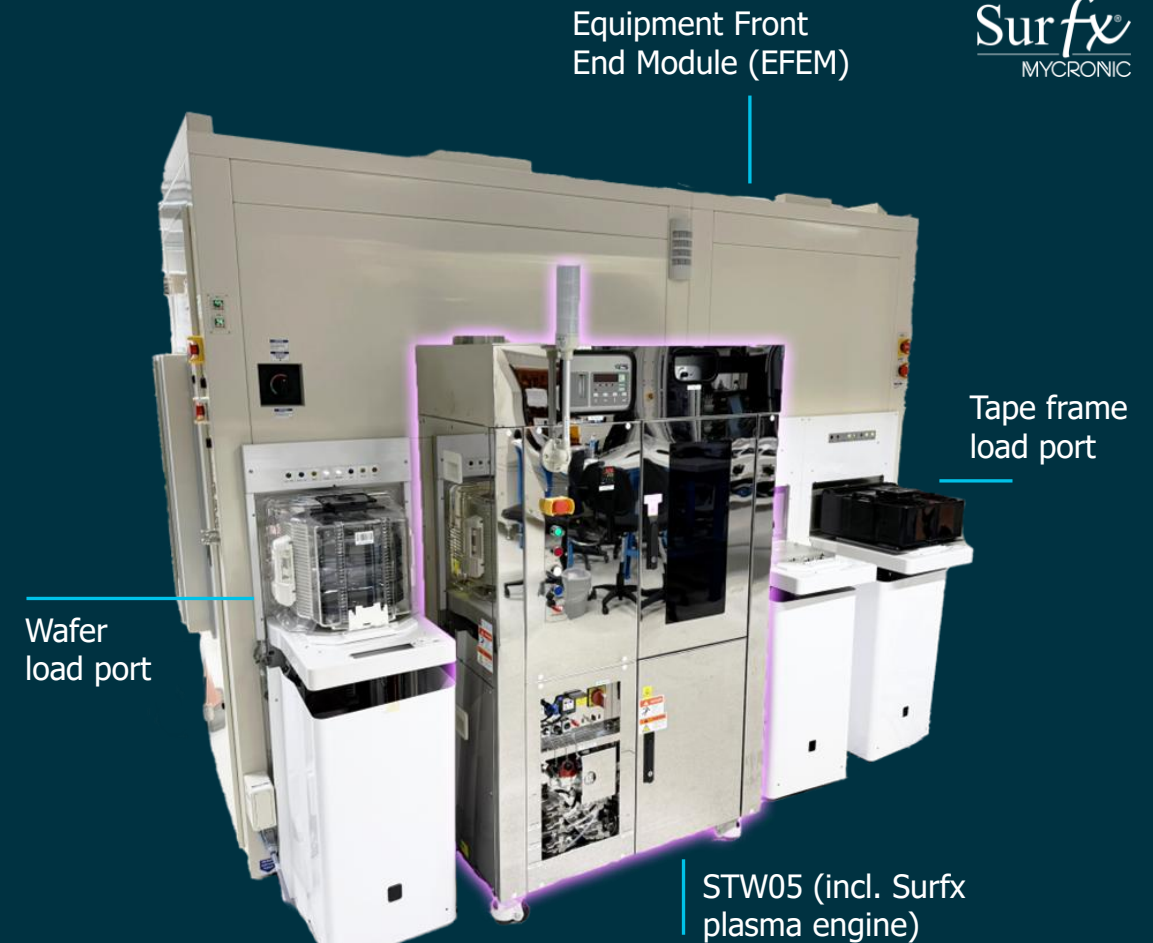
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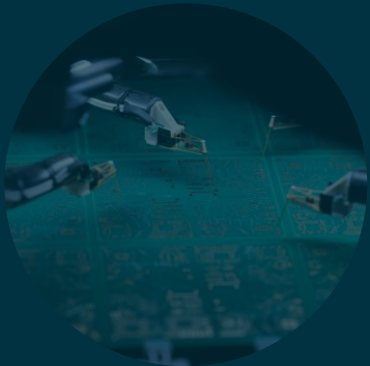


STW-series automated plasma system for semiconductor wafer processing

DIVISION

Global Technologies

PCB Test

**atg**

Market leader in Flying Probe Test solutions for the bare board PCB segment

atg
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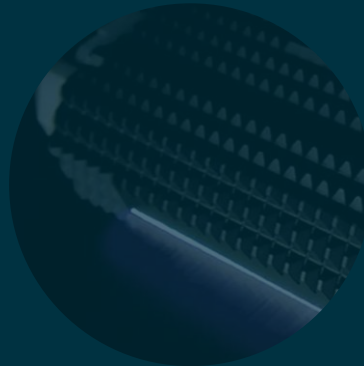
Die Bonding

**MRSI**

Leading provider of high precision die bonding, fluid dispensing, and active alignment solutions

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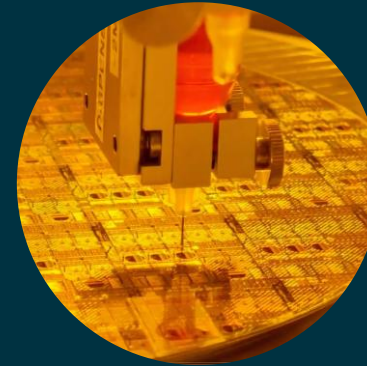
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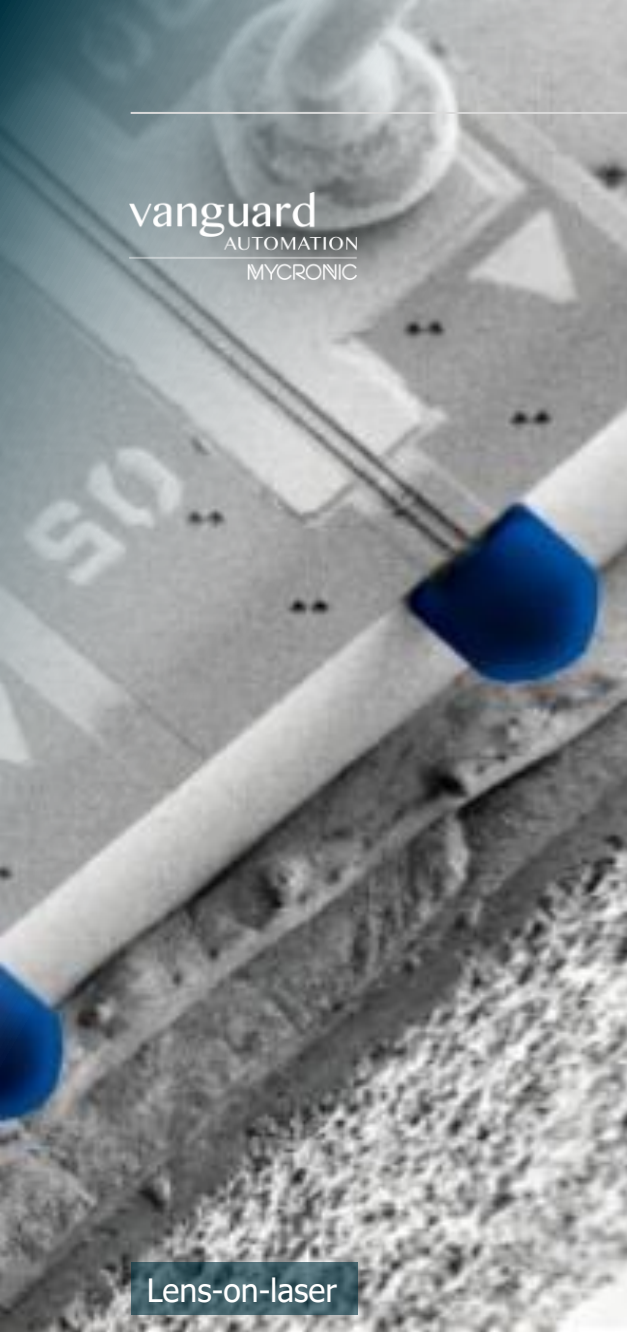
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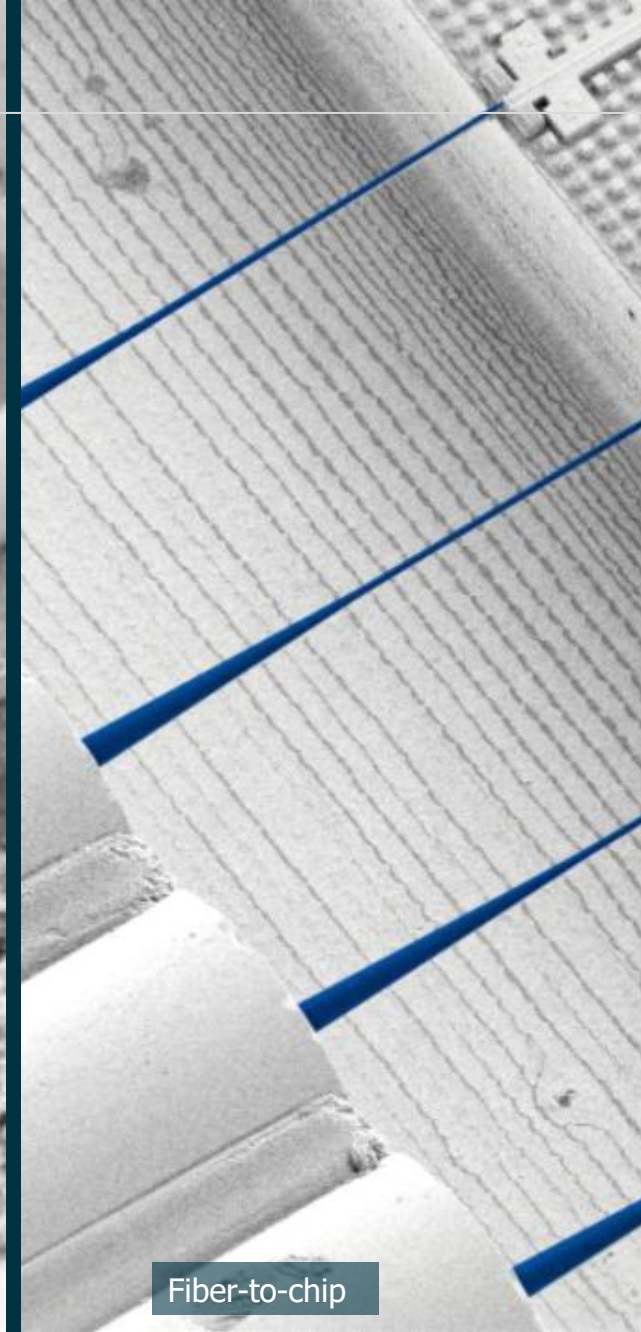
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Lens-on-laser



Fiber-to-chip

Photonic Interconnects

Enabling next-generation optical connectivity

What it does

Connecting optical chips and fiber-optic cables through 3D laser nano-printing

Platforms

- REPRISE1000: dispensing, cleaning, and cladding
- SONATA1000: 3D nano-printing

Why it matters

- Simplifies optical assembly by printing optical connections directly onto components
- Reduces complex alignment steps and component count
- An alternative to more complex heterogeneous integration

Customers

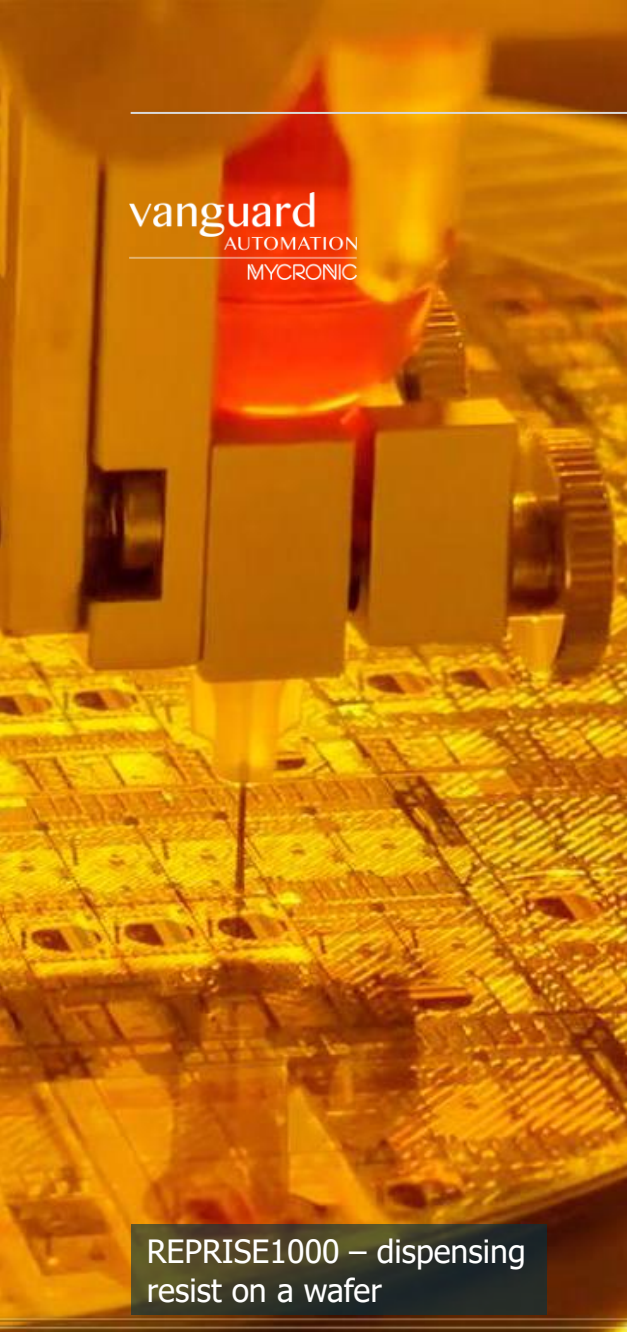
- Leading suppliers of optical transceivers and External Light Sources (ELS) for AI data center interconnects

Market drivers

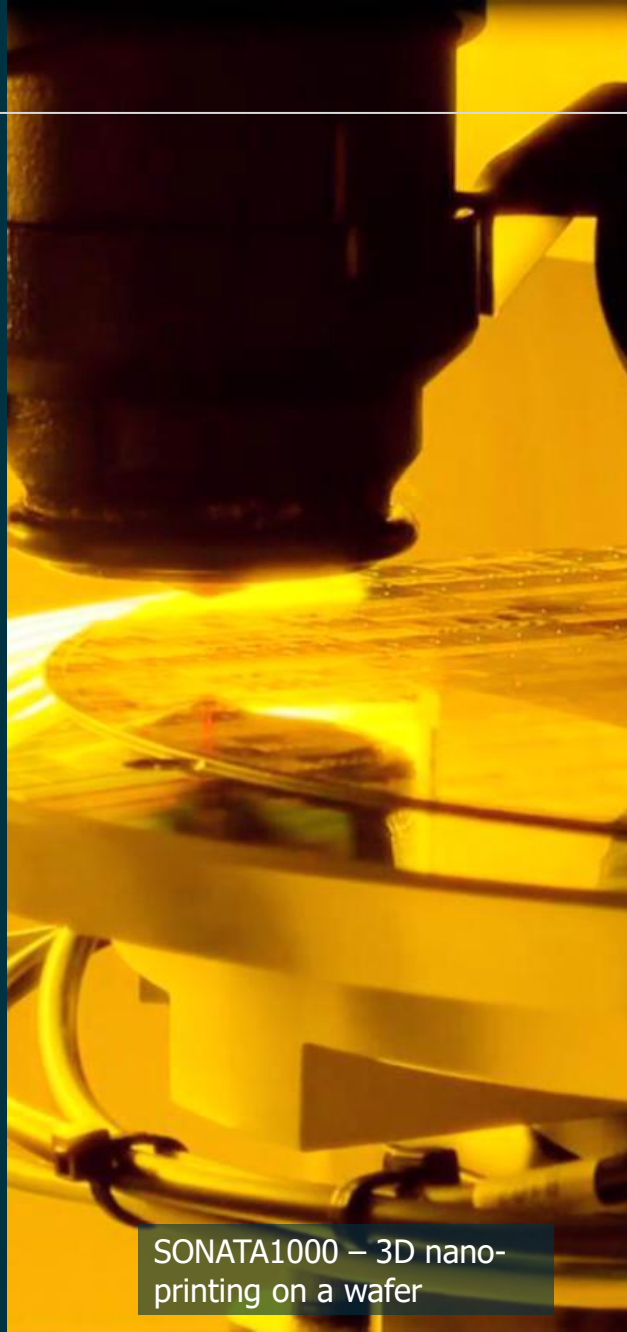
- **AI-driven** optical interconnect demand
- Increasing bandwidth within and between servers



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REPRISE1000 – dispensing
resist on a wafer



SONATA1000 – 3D nano-
printing on a wafer

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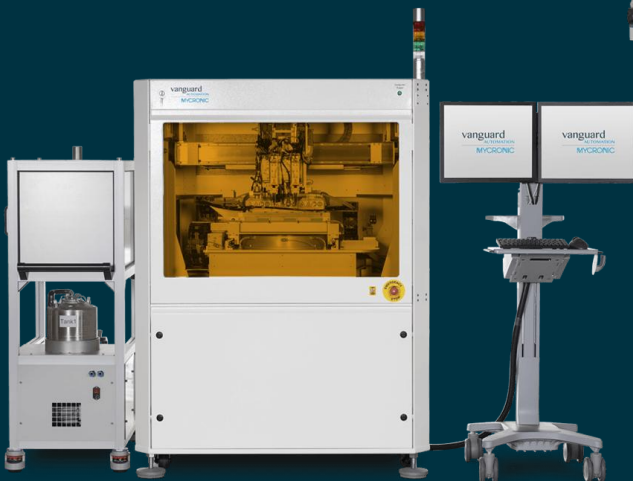
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3 x SONATA1000 –
automated 3D lithography-
based nano fabrication



1 x REPRISE1000 –
automated pre- and
postprocessing

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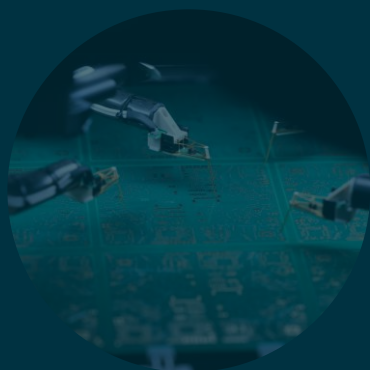
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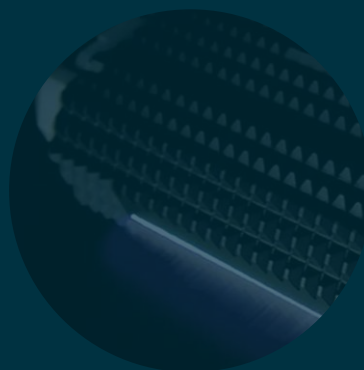
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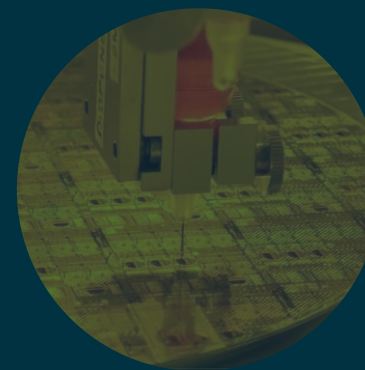
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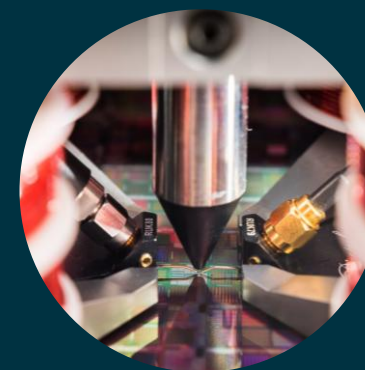
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Magnetic Test

Enabling next-generation MRAM and magnetic sensors

What it does

Automated test systems for characterization and validation of **MRAM** devices and **magnetic sensors** under magnetic fields

Differentiation

- High-speed, high-precision 3D magnetic field generation

Why it matters

- Ensures performance, reliability, and yield of magnetic semiconductor devices
- Supports the full product lifecycle from R&D to high-volume

Customers

- Leading MRAM and magnetic sensor manufacturers, including major foundries, serving automotive, industrial, and edge computing applications

Market drivers

- Adoption of MRAM as next-generation non-volatile memories
- Growing semiconductor content in automotive and industrial
- Increasing demand for low-power, high-reliability edge AI and sensing devices

Hprobe
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Inside Hprobe test head

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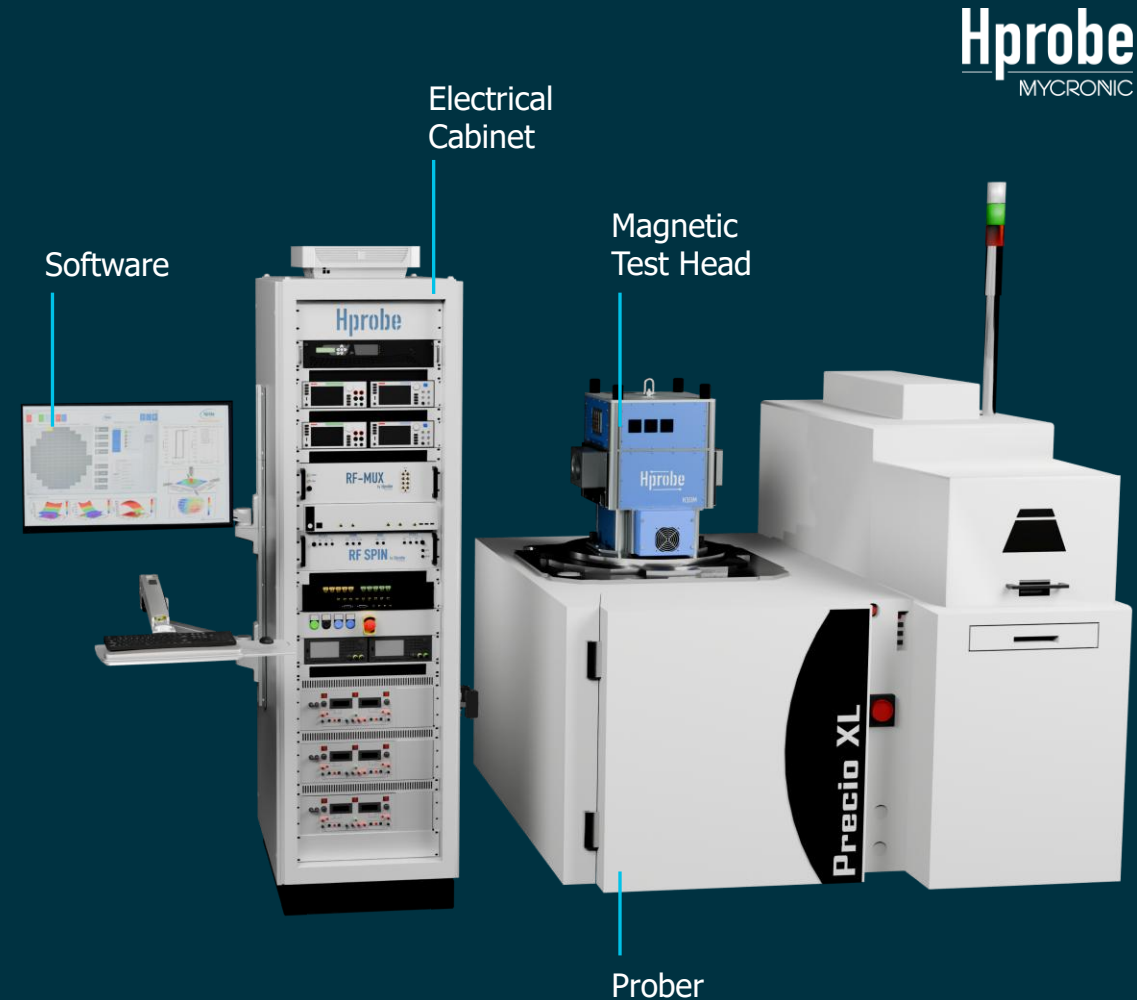
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Full Hprobe tester

Division **Global Technologies**

PCB Test

Capitalize on AI build-out and introduce TDR as a complement to back drill test for PCBs

Die Bonding

Capitalize on growth in AI-related infrastructure and rising investment in defense industry

Applied Plasma

Replace incumbent vacuum plasma in semiconductor production with atmospheric plasma

Photonic Interconnects

Become the process of record for laser integration in next-generation optical connectivity

Magnetic Test

Become the go-to provider of *all* MRAM and magnetic device tests

Division **Global Technologies**

GT is more than a collection of businesses – it is a **growth engine** that identifies differentiated technology leaders in attractive niches, accelerates their growth through Mycronic's global platform, and builds **industry-leading divisions of tomorrow**



**Technology
and market** leader
in attractive
electronics niches

Capital Markets Day 2026

Anders Lindqvist

President and CEO

Mycronic's position today

Well-positioned for the future

1

Supported by strong fundamentals

- Electronics industry grows more than GDP
 - AI and AI infrastructure
 - Automation
 - Electrification
 - Energy transition

2

Leading positions across niches

- Supplying differentiating technologies
- Global reach – local presence
- Leading in niches

3

Organizational design – Scalability

- Divisional structure -> Act fast close to customers
- Proven ability to scale

4

Collective knowledge

- Well embedded in the electronics industry
- Highly competent and motivated global workforce

5

Bold market-driven investments – Organic and M&A

- PG – SLX, Inspection and acquisition of Repair
- HV – Adding new industries and geographies
- SurfX – New emerging technology
- atg – Niche leader

6

Geopolitically well-positioned

- Well-suited to serve different global markets
- Operational design continuously adapted to manage geopolitics
- Solid protection of IP and technology
- Continuous focus on trade compliance

Mycronic's formula for sustainable, profitable growth

Ambition is to continue the growth trajectory

1

Invest in profitable businesses, supported by a strong cash-flow and balance sheet

- Continue investing in R&D
- Continue investing in M&A
- Invest in organizational footprint
- Invest in modern facilities

2

Enter new areas

- Continuously be open to new opportunities with potential in the electronics industry, in accordance with selected parameters
- Give priority to further investments in wafer, semicon assembly, packaging and test, organically as well as through M&A

3

Customer partnering

- True customer partner
- Divisions with mandate to act close to customers
- Excellence in Aftermarket

4

Organizational development

- Best organization in the industry
- Further improve organizational efficiency
- Continuing to grow diverse talent and leadership

5

Navigate the geopolitical landscape

- Capitalize on opportunities and manage risks in a divided world
- Design operations for optionality
- Optimize supply chain

6

Reducing climate impact

- Support customers' emissions reduction through innovative and energy efficient products
- Ensure a minimal own environmental footprint
- Leverage the clean energy trend
- Collaborate within the industry to reduce climate impact

Capital Markets Day 2026

Q&A

Bringing tomorrow's electronics to life

MYCRONIC